

# HD63487

## Memory Interface and Video Attribute Controller (MIVAC)



Rev. 1  
Feb. 1990

The MIVAC belongs to the HD63484 ACRTC (Advanced CRT controller) family. It includes peripheral control circuits for graphic display on a chip. Incorporating bus driver circuits and a DRAM interface, the MIVAC allows direct connection to DRAMs with no external circuits. On-chip parallel/serial converting shift register generates high speed video signals. Adopting static column mode, fast memory access achieves high throughput in spite of narrow memory data bus. The MIVAC provides most functions required at peripherals of a frame buffer for graphic display constructed with 1 to 4 memory chips, and enables small size graphic system easily. Using the Hi-BiCMOS process, the MIVAC achieves high speed memory access with low power dissipation.

### Features

- Directly connected with 1 to 4 memory devices ( $\times 4$  bit organization, static column mode)
- Generates DRAM interface signals: row and column address, RAS, CS, OE, WE and memory data
- Generates high speed video signal: dot rate of 33 MHz (max)
- 16 kinds of operation modes by the combination of;
  - 2, 4 and 16 colors (1, 2 and 4 bit/pixel)
  - 8, 16 and 32 dot shift
  - Single/dual access
  - 1, 2 and 4 chips memory
- Blinking block cursor display
- Memory variation: 256 k  $\times$  4 static column mode DRAM
- Generates special clock to drive the ACRTC (asymmetrical 2CLK)
- Input clock divider to generate dot clocks (divided by 1, 2 and 4)
- Supports frame sequential application
  - $\overline{VSYNC}$  divider and  $VSYNC/2$  output
  - 4  $\rightarrow$  2 bit video output multiplexer
- BLINK2 interrupting control ( $\overline{BL2IRQ}$  output)
- $\overline{CS}$  before  $\overline{RAS}$  refresh
- Direct interface with the ACRTC
- Supports hardware window of ACRTC
- TTL compatible input/output
- Single +5 V power supply
- Low power dissipation

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## Pin Assignment

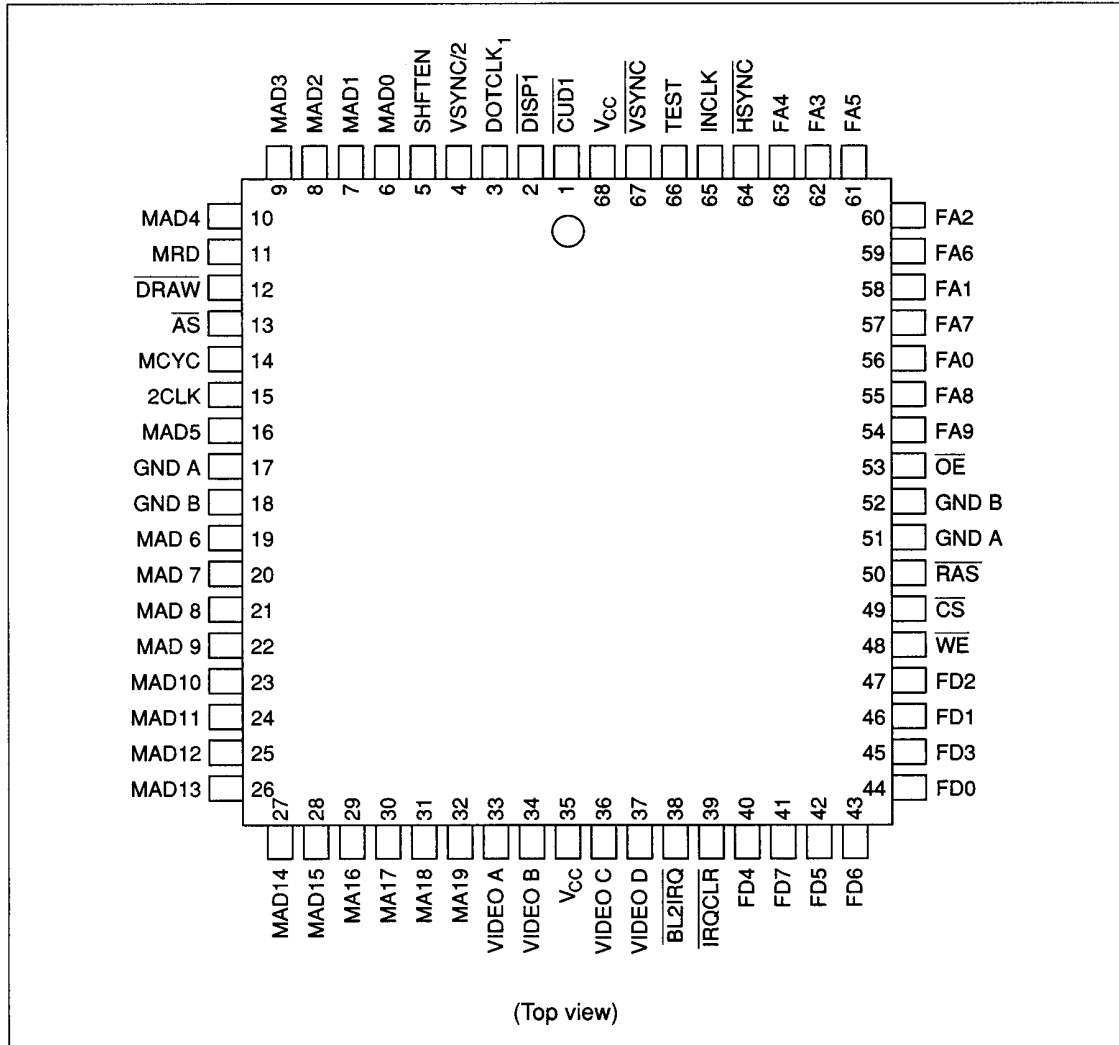
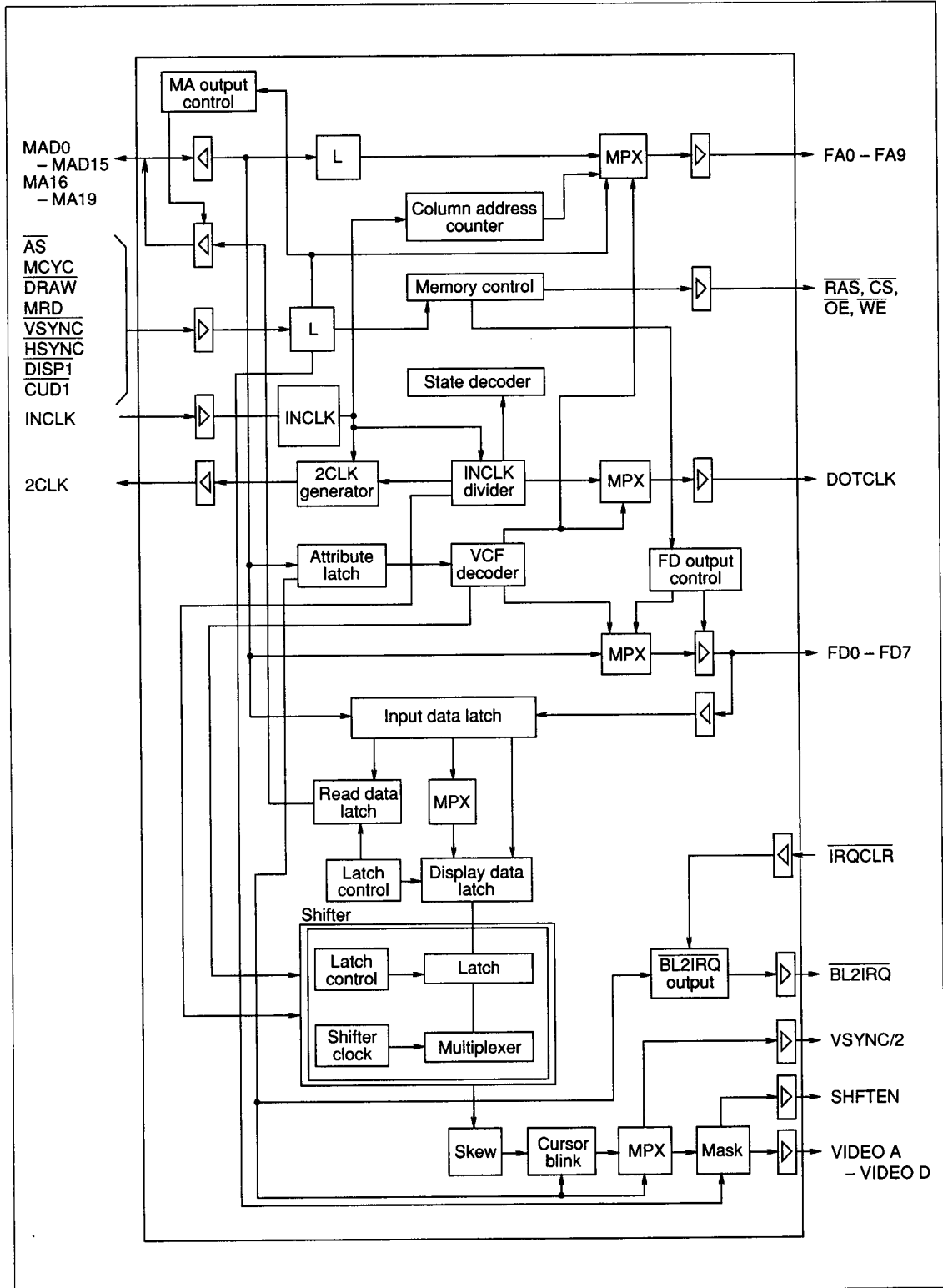


Table 1 Function Table

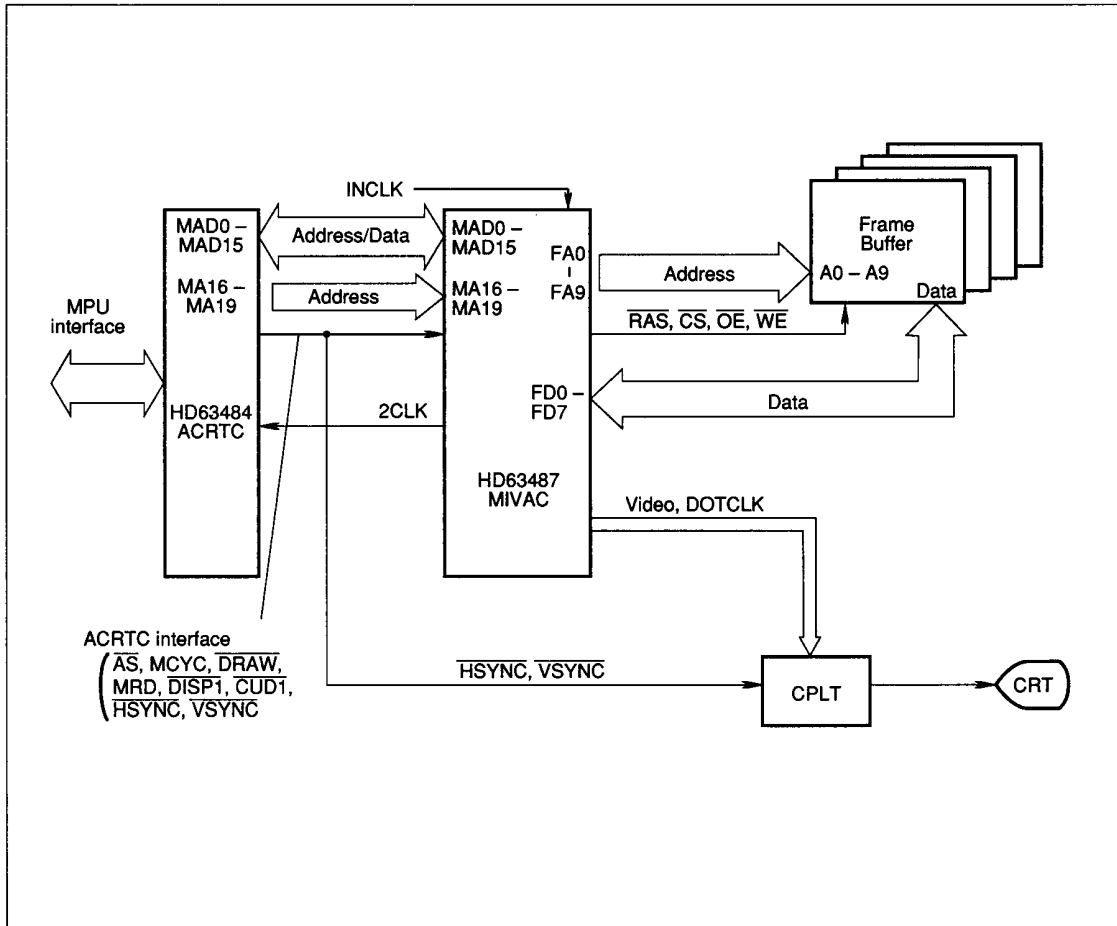
Mode	Attribute code (ACRTC)				MCYC fetch	Access mode	Memory chip	Bit/ pixel	Shifted dot	DOTCK division
	MAD3	MAD2	MAD1	MAD0						
0	0	0	0	0	1	Single	1	1	16	1
1	0	0	0	1	1	Single	1	2	8	2
2	0	0	1	0	1	Single	1	4	4	4
3	0	0	1	1	1	Single	2	2	16	1
4	0	1	0	0	1	Single	2	4	8	2
5	0	1	0	1	1	Single	4	4	16	1
6	0	1	1	0	1	Dual	1	1	16	2
7	0	1	1	1	1	Dual	1	2	8	4
8	1	0	0	0	1	Dual	2	1	32	1
9	1	0	0	1	1	Dual	2	2	16	2
A	1	0	1	0	1	Dual	2	4	8	4
B	1	0	1	1	1	Dual	4	2	32	1
C	1	1	0	0	1	Dual	4	4	16	2
D	1	1	0	1	2	Single	1	2	32	1
E	1	1	1	0	2	Single	1	4	16	2
F	1	1	1	1	2	Single	2	4	32	1

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## Block Diagram



System Application Example



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### Power Supply ( $V_{CC}$ , $V_{SS}$ )

$V_{SS}$  and  $V_{CC}$  are the MIVAC power supply pins.  $V_{CC}$  pins are +5 V  $\pm$  5% supply pins.  $V_{SS}$  are the ground pins. Be sure to connect all four  $V_{SS}$  pins to ground and both  $V_{CC}$  pins to the power supply.

### Operation Control Signals

In clock (INCLK): This is basic operating clock for the MIVAC.

Test (TEST): The TEST input is used for manufacturing operational testing. It must be fixed low when the MIVAC is mounted in a system.

### ACRTC Interface Signals

Clock (2CLK): The 2CLK clock output is a basic clock for the ACRTC's internal operation. The MIVAC generates 2CLK by dividing the INCLK.

Memory cycle (MCYC): The ACRTC's MCYC output supplies this input. The MCYC input indicates the ACRTC's frame buffer access timing. MCYC is low when the ACRTC is in the address cycle, and high when the ACRTC is in the data cycle.

Draw ( $\overline{DRAW}$ ): The ACRTC's  $\overline{DRAW}$  output supplies this input. The  $\overline{DRAW}$  input indicates whether the ACRTC memory cycle is a drawing cycle.  $\overline{DRAW}$  is low during drawing cycle, and high otherwise. The MIVAC uses  $\overline{DRAW}$  to recognize display cycles, and also to generate DRAM control signals.

Memory read (MRD): The ACRTC's MRD output supplies this input. The MRD input controls data transfer between frame buffers and the ACRTC. The ACRTC pulls MRD high when it reads data from the frame buffer, and low when it writes data.

Address strobe ( $\overline{AS}$ ): The ACRTC's  $\overline{AS}$  output supplies this input. The  $\overline{AS}$  input is a latch timing signal for the memory address sent from the ACRTC. Additionally,  $\overline{AS}$  indicates whether memory is begun accessed.

Horizontal sync ( $\overline{HSYNC}$ ): The ACRTC's  $\overline{HSYNC}$  output supplies this input. The  $\overline{HSYNC}$  input is a DRAM refresh cycle control signal to horizontally synchronize CRT displays. The MIVAC performs  $\overline{CS}$  before  $\overline{RAS}$  refresh when  $\overline{HSYNC}$  is low and  $\overline{DRAW}$  is high when AS pulses are input.

Vertical sync ( $\overline{VSYNC}$ ): The ACRTC's output supplies this input. The MIVAC internally divides  $\overline{VSYNC}$  by 2 to generate the VYNCS/2 output.

Display 1 ( $\overline{DISP1}$ ): The ACRTC's  $\overline{DISP1}$  output supplies this input. It indicates the screen's display period. Usually, the ACRTC's DSP (display signal control) bit is set to 1.

Cursor display 1 ( $\overline{CUDI}$ ): The ACRTC's  $\overline{CUDI}$  output supplies this input. It is low when the graphic cursor is display period.

Memory address/data 0 – 15 (MAD0 – MAD15): The ACRTC's MAD0 – MAD15 output supplies this input. When MCYC is low, MAD0 – MAD15 indicate the frame buffer address. When MCYC is high, they transfer the drawing data to and from the frame buffer.

Memory address 16 – 19 (MA16 – MA19): The ACRTC's address MA16 – MA19 for frame buffer access supplies this input.

### Frame Buffer Access Signals

Row address strobe ( $\overline{RAS}$ ): The MIVAC outputs the DRAM's  $\overline{RAS}$  timing signal on the  $\overline{RAS}$  output.

Chip select ( $\overline{CS}$ ): The MIVAC outputs the DRAM's  $\overline{CS}$  timing signal on the  $\overline{CS}$  output.

Write enable ( $\overline{WE}$ ): The MIVAC outputs the DRAM's  $\overline{WE}$  timing signals on the  $\overline{WE}$  outputs.

Output enable ( $\overline{OE}$ ): The MIVAC outputs the DRAM's output timing signal on the  $\overline{OE}$  output.

Frame buffer address (FA0 – FA7): The MIVAC outputs the multiplexed DRAM address on FA0 – FA7.

**Frame Buffer Data (FD0 – FD7)**

The 8 bits FD0 – FD7 frame buffer data I/O bus transfers data between the ACRTC and frame buffers and inputs display data from the frame buffers. In 1 chip memory mode, FD0 – FD3 is used. In 2 or 4 chips memory mode, FD0 – FD7 is used.

**CRT Display Interface**

**Dot clock (DOTCLK):** The MIVAC internally divides INCLK by 1, 2 or 4 to generate the DOTCLK output. DOTCLK division ratio depends on VCF0 – VCF3 of attribute code.

**Video outputs (VIDEOA – VIDEOD):** VIDEOA – VIDEOD are the four bits output from the MIVAC's parallel-to-serial conversion shift register. They are supplied during a display period specified by the display signal (DISP). Which outputs are usable depends on the attribute code (VCF0 – VCF3).

**Shift enable (SHFTEN):** SHFTEN is active high output. This output indicates the active display period of the screen.

**Vertical sync divide-by-2 (VSYNC/2):** VSYNC/2 output is  $\overline{\text{VSYNC}}$  signal from the ACRTC divided by two.

**Others**

**BLINK2 interrupt ( $\overline{\text{BL2IRQ}}$ ):** This output is sat by BLINK2 (MA19) of the attribute code.  $\overline{\text{BL2IRQ}}$  is low when BLINK2 is high.

**BLINK2 interrupt clear ( $\overline{\text{IRQCLR}}$ ):** This input clears the  $\overline{\text{BL2IRQ}}$  signal. When  $\overline{\text{IRQCLR}}$  is low,  $\overline{\text{BL2IRQ}}$  is clear and high.

**Table 2 Pin Description**

Pin No.	Signal	Description
68	$V_{CC}$	Power
35		
52	$V_{SS}$	Logic ground
51		
18		
17		
15	2CLK	Output clock to the ACRTC
14	MCYC	Memory cycle input from the ACRTC
12	$\overline{\text{DRAW}}$	Draw input from the ACRTC
11	MRD	Memory read input from the ACRTC
13	$\overline{\text{AS}}$	Address strobe input from the ACRTC

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**Pin Description (cont)**

<b>Pin No.</b>	<b>Signal</b>	<b>Description</b>
6	MAD0	Multiplex frame buffer address/data to/from ACRTC
7	MAD1	
8	MAD2	
9	MAD3	
10	MAD4	
16	MAD5	
19	MAD6	
20	MAD7	
21	MAD8	
22	MAD9	
23	MAD10	
24	MAD11	
25	MAD12	
26	MAD13	
27	MAD14	
28	MAD15	
29	MA16	Memory address line 16 from the ACRTC
30	MA17	Memory address line 17 from the ACRTC
31	MA18	Memory address line 18 from the ACRTC
32	MA19	Memory address line 19 from the ACRTC
64	$\overline{\text{HSYNC}}$	Horizontal sync input from the ACRTC
67	$\overline{\text{VSYNC}}$	Vertical sync input from the ACRTC
4	VSYNC/2	Vertical sync divide-by-2 output
1	$\overline{\text{CURD1}}$	Cursor control input from the ACRTC
2	$\overline{\text{DISP1}}$	Display input from the ACRTC
50	$\overline{\text{RAS}}$	Row address strobe output to DRAM
49	$\overline{\text{CS}}$	Chip select output to DRAM
48	$\overline{\text{WE}}$	Write enable output to DRAM
53	$\overline{\text{OE}}$	Output enable output to DRAM
56	FA0	Frame buffer (memory) address output 0



**Pin Description (cont)**

<b>Pin No.</b>	<b>Signal</b>	<b>Description</b>
58	FA1	Frame buffer (memory) address output 1
60	FA2	Frame buffer (memory) address output 2
62	FA3	Frame buffer (memory) address output 3
63	FA4	Frame buffer (memory) address output 4
61	FA5	Frame buffer (memory) address output 5
59	FA6	Frame buffer (memory) address output 6
57	FA7	Frame buffer (memory) address output 7
55	FA8	Frame buffer (memory) address output 8
54	FA9	Frame buffer (memory) address output 9
44	FD0	Frame buffer data input/output line 0
46	FD1	Frame buffer data input/output line 1
47	FD2	Frame buffer data input/output line 2
45	FD3	Frame buffer data input/output line 3
40	FD4	Frame buffer data input/output line 4
42	FD5	Frame buffer data input/output line 5
43	FD6	Frame buffer data input/output line 6
41	FD7	Frame buffer data input/output line 7
65	INCLK	Main timing clock input
3	DOTCLK	DOT clock output to video circuit
33	VIDEOA	Video A output
34	VIDEOB	Video B output
36	VIDEOC	Video C output
37	VIDEOD	Video D output
66	TEST	Test pin input
5	SHFTEN	Shift enable output
38	BLINK2 $\overline{IRQ}$	BLINK2 interrupt output
39	IRQCLR	BLINK2 interrupt clear input

**Operation****Basic Operating Clock**

Output signals from MIVAC define INCLK which inputs to MIVAC as a basic operating clock, and input signals to MIVAC define 2CLK which is output from MIVAC as well. 2CLK, the basic operating clock of ACRTC which is output from MIVAC, is generated from INCLK. In order to save the memory access time, 2CLK is configured unsymmetrically between the first half and the latter half of cycle times as shown below.

**Frame Buffer Control**

MIVAC uses the DRAM of the static column mode as a memory for the frame buffer, and reduces the number of memory used for the frame buffer by accessing the memory several times per memory cycles. Using one, two, and four DRAMs respectively, MIVAC can deal with various kinds of applications. Figure 2 shows the connection of MIVAC to the DRAM.

To control these DRAMs, MIVAC generates  $\overline{\text{RAS}}$ ,  $\overline{\text{CS}}$ ,  $\overline{\text{OE}}$  and  $\overline{\text{WE}}$ . And it outputs the row and the column address as the ones for DRAM, adapting to the timing of  $\overline{\text{RAS}}$  and  $\overline{\text{CS}}$ .

The drawing read cycle is shown in figure 3, the drawing write cycle in figure 4, the display read cycle in figure 5 and 6, and  $\overline{\text{CS}}$  before RAS refresh cycle in figure 7 respectively.

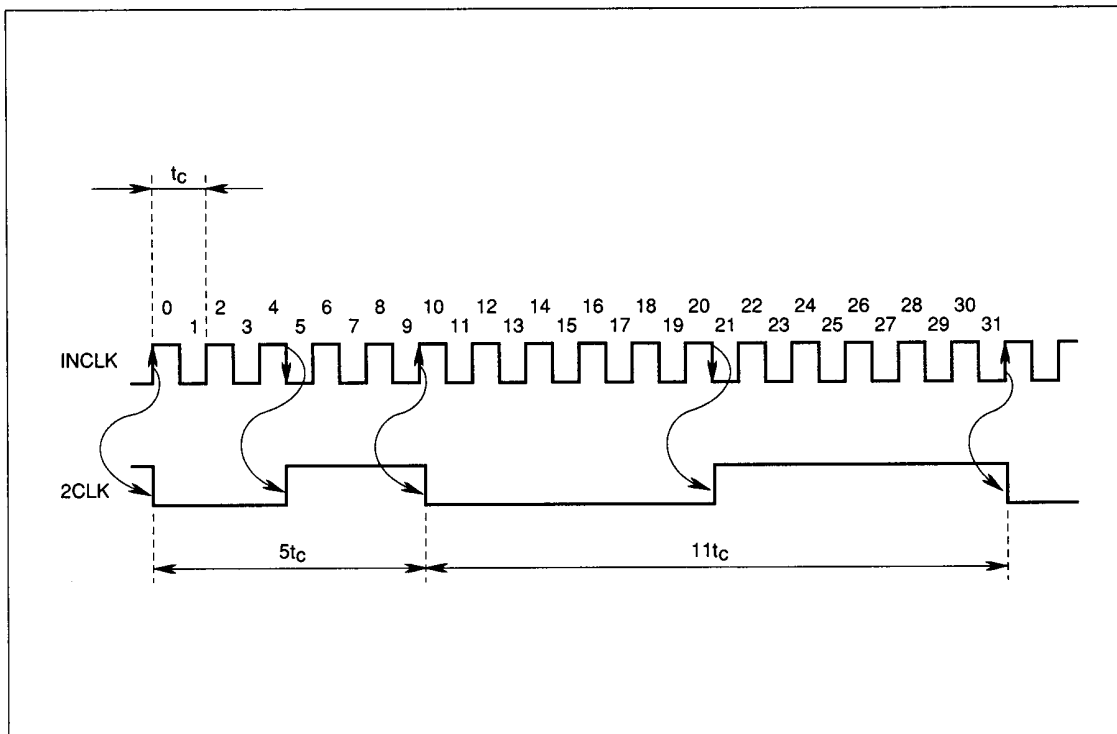


Figure 1 2CLK Output Timing

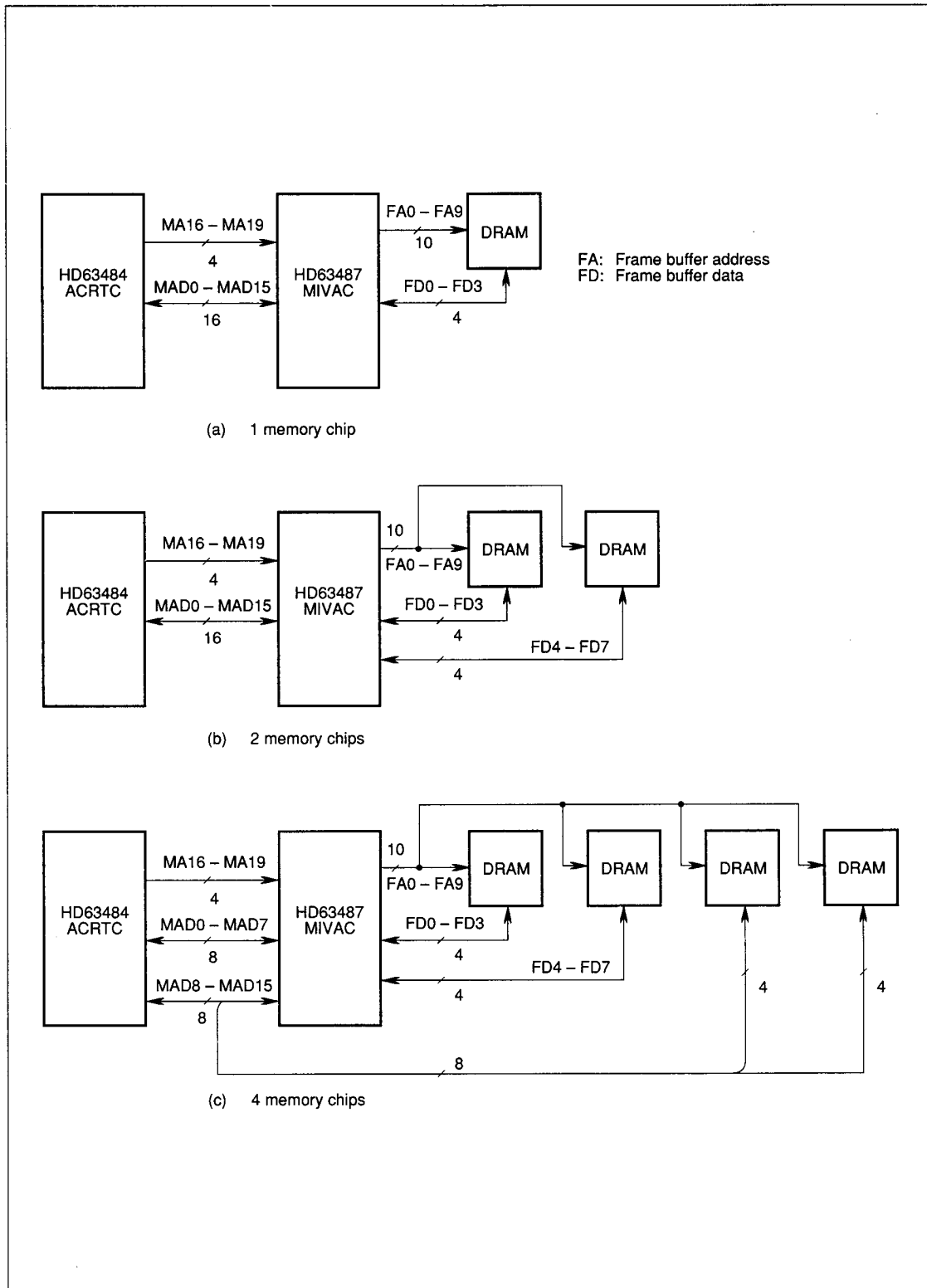


Figure 2 Frame Buffer Connections

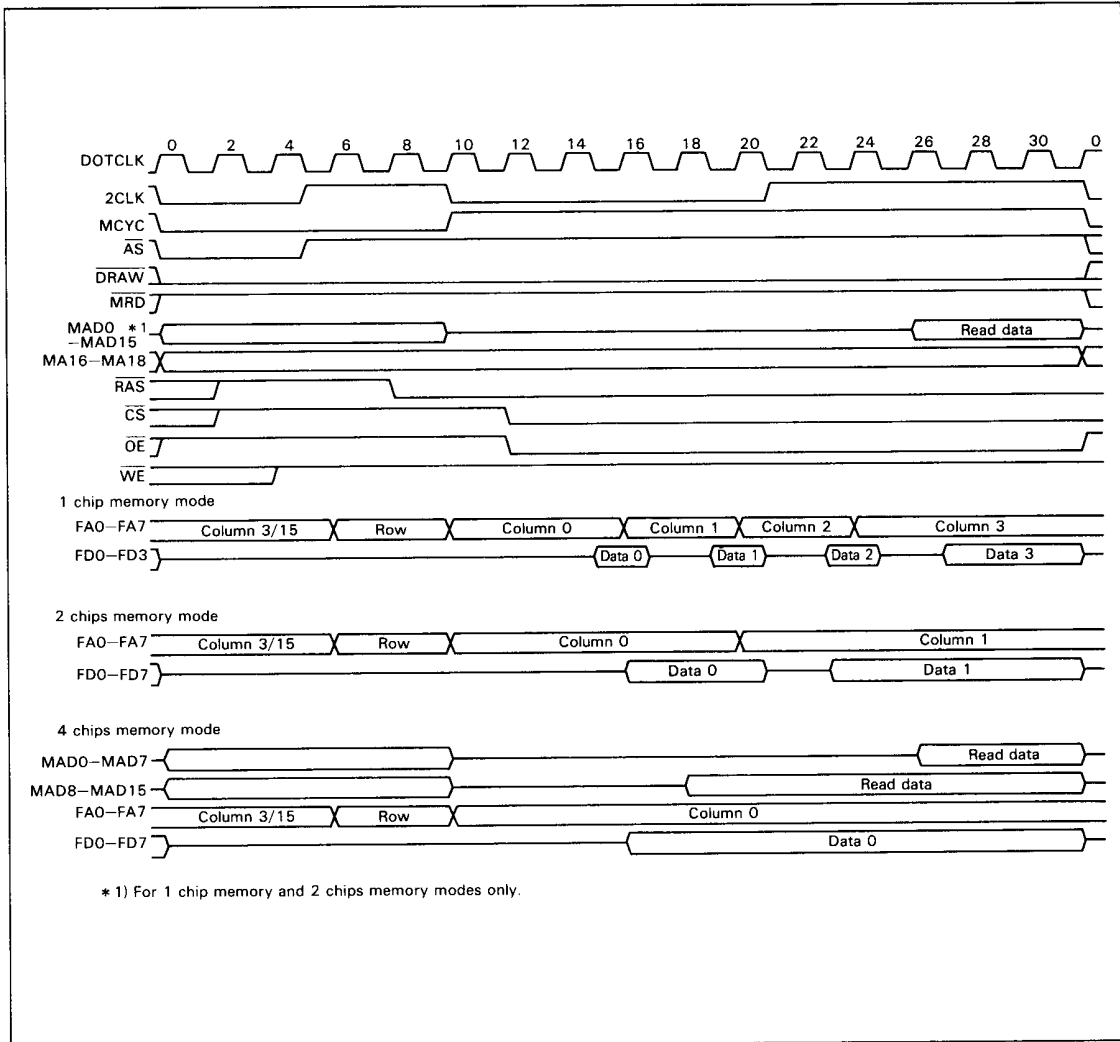


Figure 3 1M1CYC Drawing Read Cycle

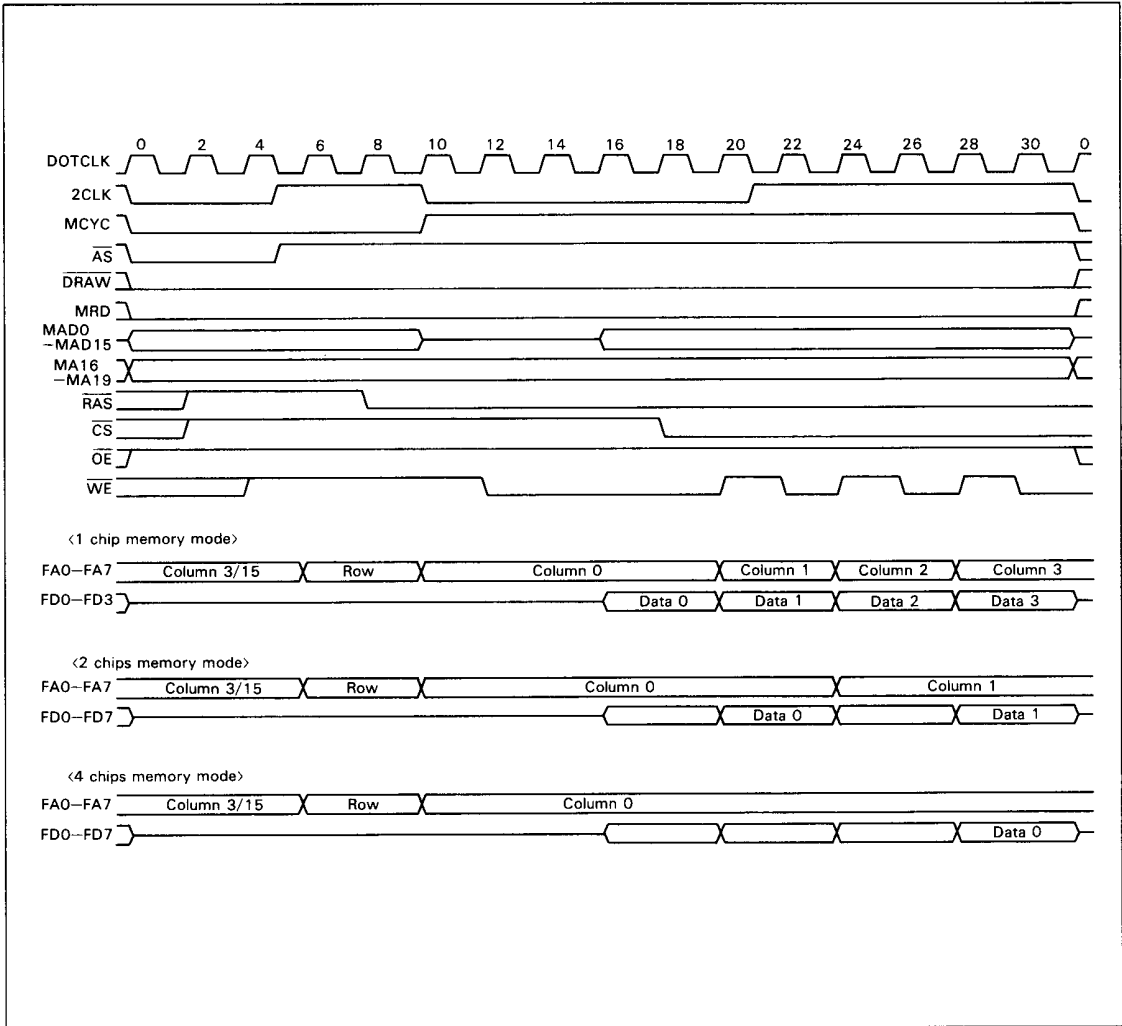


Figure 4 IMCYC Drawing Write Cycle

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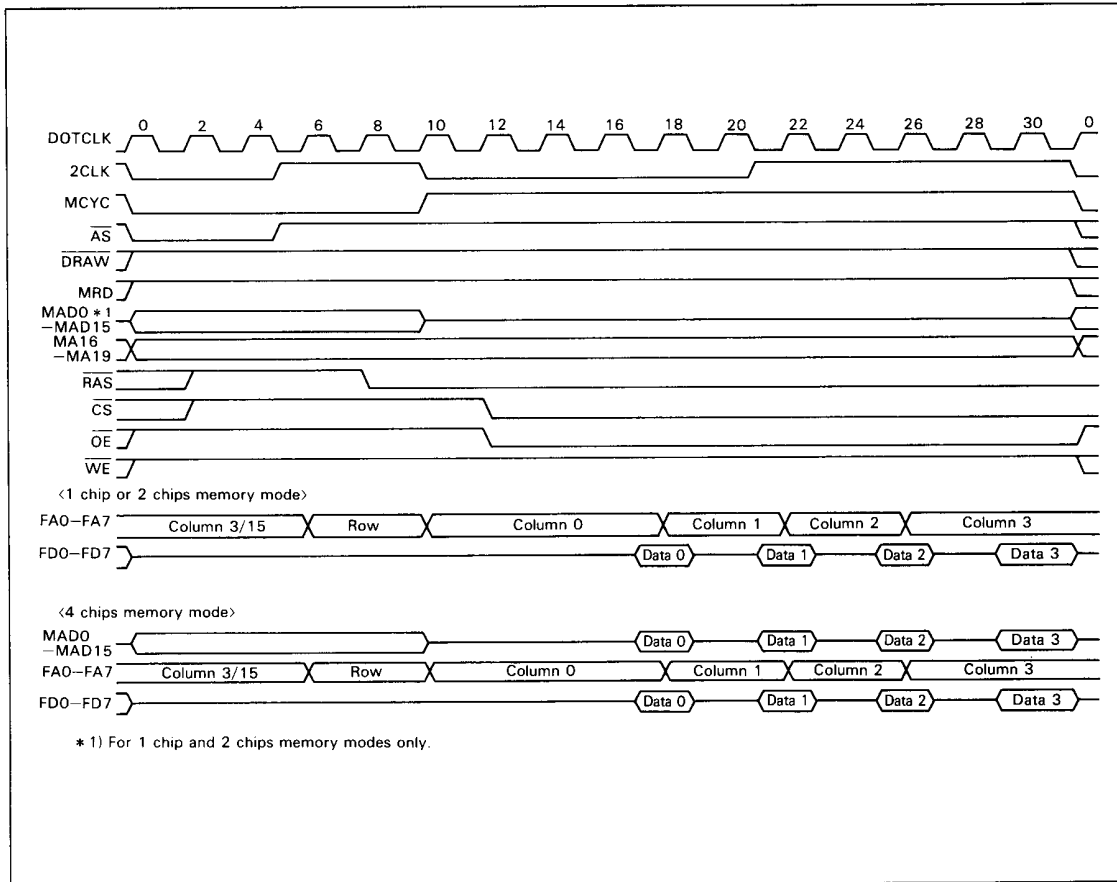


Figure 5 1MCYC Display Read Cycle

## Data Transfer

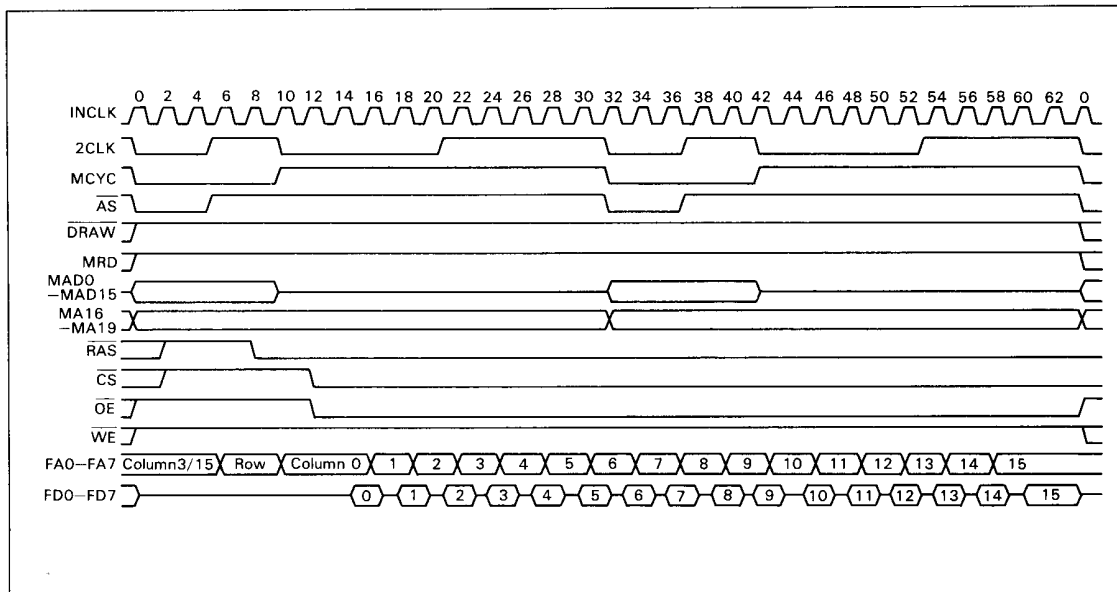


Figure 6 2MCYC Display Read Cycle

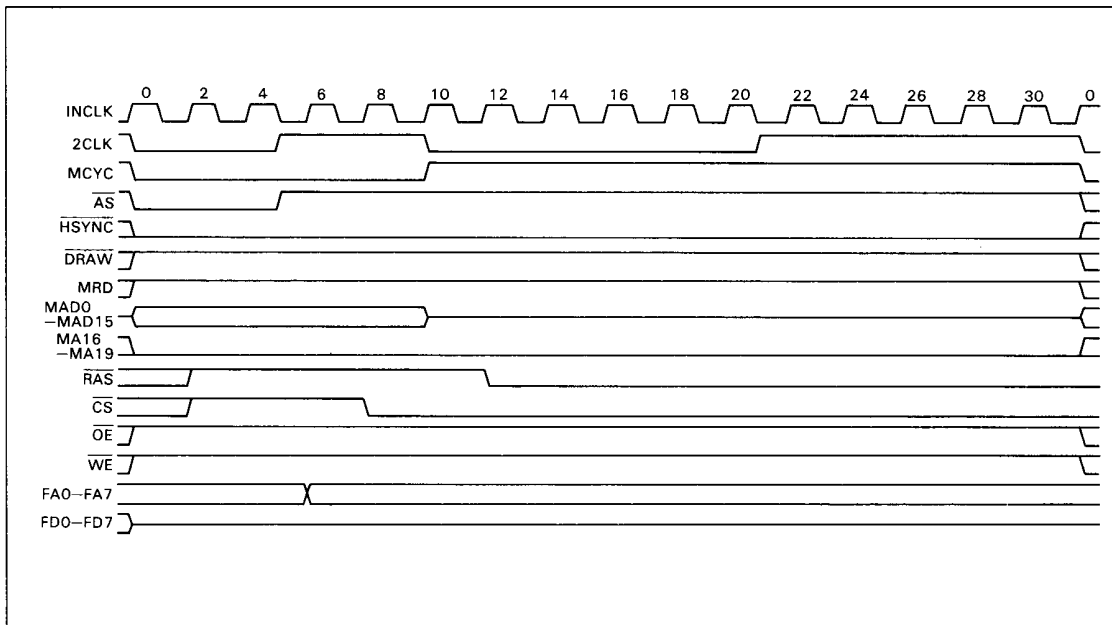


Figure 7  $\overline{CS}$  before  $\overline{RAS}$  Refresh Cycle

**Data Transfer**

The MIVAC contain control circuits for bidirectional transfer between the ACRTC and frame buffers. To transfer data, the MIVAC receive the ACRTC's memory cycle (MCYC), memory read (MRD), draw (DRAW) and address strobe ( $\overline{AS}$ ) signals.

The MIVAC recognize a nondisplay cycle when  $\overline{DRAW}$  is low. In nondisplay cycles the data transfer direction is determined by the memory read signal (MRD). MRD high signifies a read cycle to transfer data from frame buffers to the ACRTC. MRD low signifies a write cycle to transfer data from the ACRTC to the frame buffers. Timing for the data transfer is determined by the MCYC input. When MCYC is high, frame buffers or the ACRTC three-state output buffers are enabled for transfer.

Drawing write cycle: The MIVAC recognize a drawing write cycle when both  $\overline{DRAW}$  and MRD are low.

Drawing read cycle: The MIVAC recognize a drawing read cycle when  $\overline{DRAW}$  is low and MRD is high.

When MCYC is high during this cycle, the MIVAC enable the data buffer (MAD0 – MAD15) for the ACRTC and output a word from the frame buffers.

**Video Signal Generation**

MIVAC converts the parallel display data, which is output from the frame buffer, to serial in the internal shift register, and outputs the display data from VIDEOA – VIDEOD pins after making it simultaneous with DOTCLK. As the pins for VIDEOA – VIDEOD are determined by the graphic bit mode, they must be connected to CRT carefully. Table 3 shows the relation between the mode and the used pins.

Figure 8 shows the relation between the memory access and the video output.

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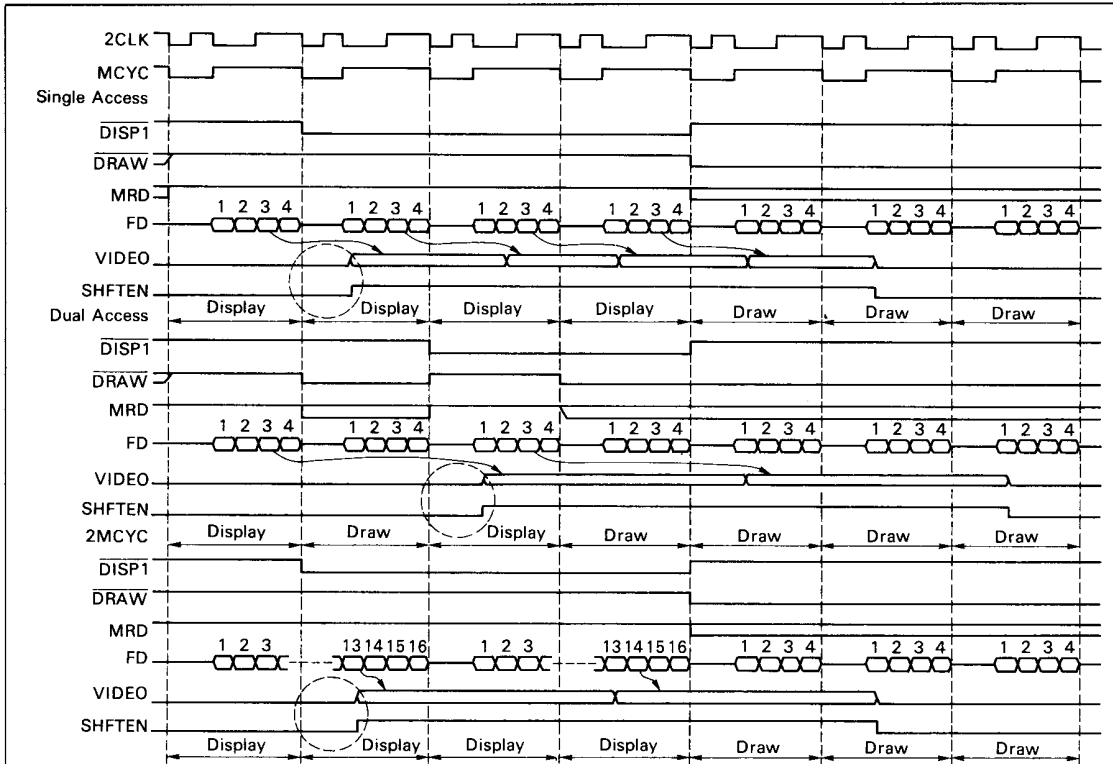
**Table 3 Operation Mode and Video Outputs**

<b>Mode</b>	<b>Graphic bit mode (bit/pixel)</b>	<b>Display colors (or gray scale)</b>	<b>VIDEOA</b>	<b>VIDEOB</b>	<b>VIDEOC</b>	<b>VIDEOD</b>
0	1	Monochrome (2)	○	×	×	×
1	2	4 (4)	○	○	×	×
2	4	16 (16)	○	○	○	○
3	2	4 (4)	○	○	×	×
4	4	16 (16)	○	○	○	○
5	4	16 (16)	○	○	○	○
6	1	Monochrome (2)	○	×	×	×
7	2	4 (4)	○	○	×	×
8	1	Monochrome (2)	○	×	×	×
9	2	4 (4)	○	○	×	×
A	4	16 (16)	○	○	○	○
B	2	4 (4)	○	○	×	×
C	4	16 (16)	○	○	○	○
D	2	4 (4)	○	○	×	×
E	4	16 (16)	○	○	○	○
F	4	16 (16)	○	○	○	○

○: Available

×: Not available





Following figure shows the detailed timing of SHFTEN and VIDEO output at sign of ○.

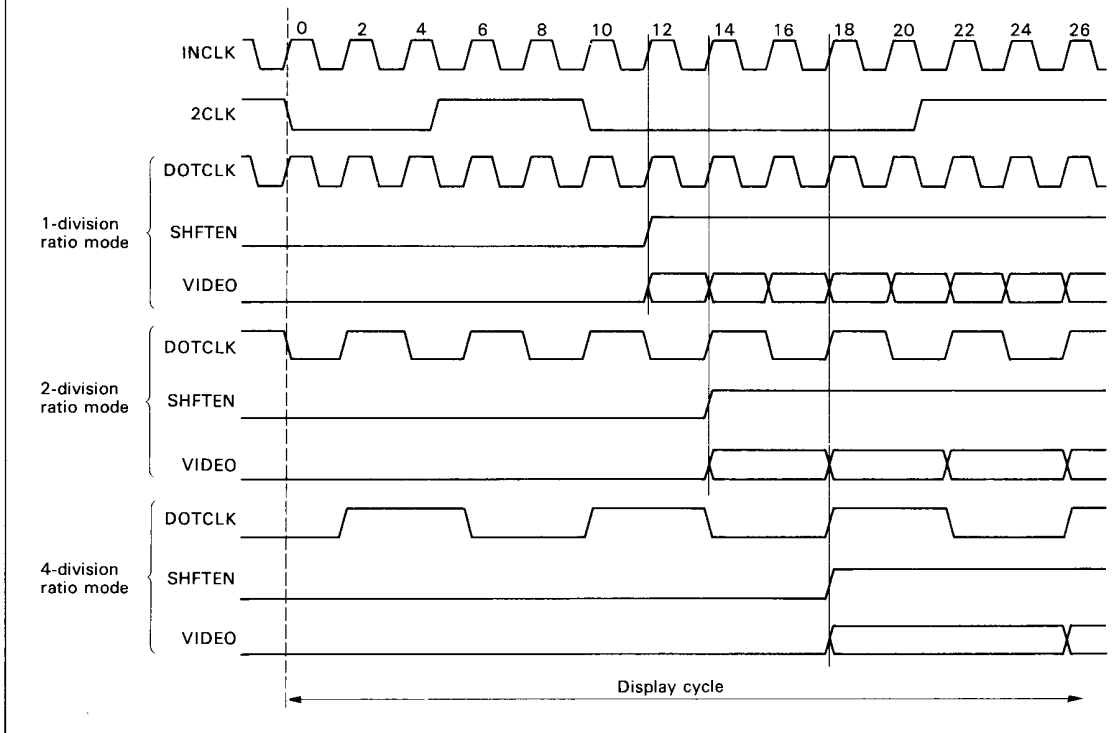


Figure 8 Display Timing (Single Access, Dual Access, 2M CYC)

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## Attribute Control Codes

The MIVAC sets colors, the number of shift bits, and access mode when it receives attribute codes and blink information from the ACRTC. The ACRTC outputs 20 bits of attribute control codes

(MAD0 to MAD15, MA16 and MA19) during the attribute control code output cycle (figure 9). This information includes user-definable codes and blink control codes (figure 10).

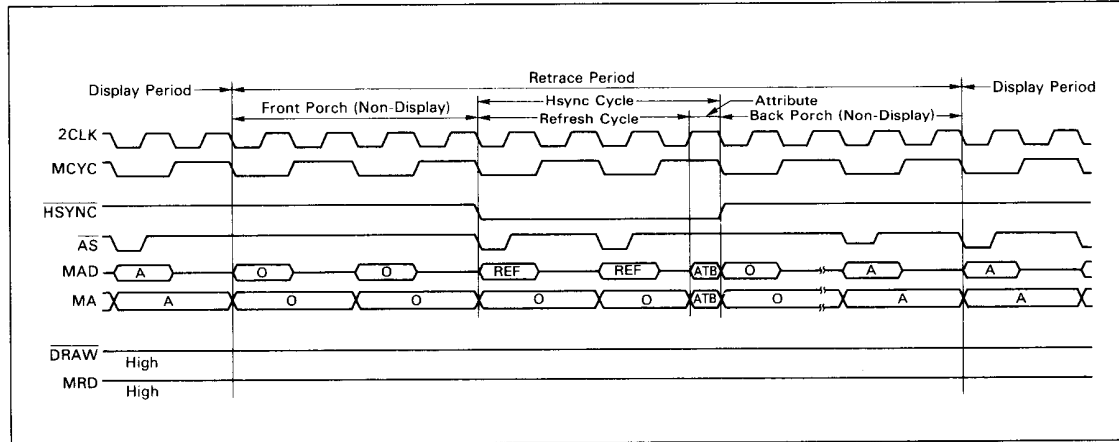


Figure 9 DRAM Refresh and Attribute Code Output Timing (Single Access Mode)

Signal	Attribute Control Codes	
MA19	BLINK2	BL2IRQ output
MA18	BLINK1	
MA17	SPL2	Graphic cursor cursor blinking
MA16	SPL1	
MAD15	HZ3	MIVAC does not use
{	{	
MAD12	HZ0	
MAD11	HSD3	
{	{	
MAD8	HSD0	Video multiplex output enable
MAD7	MUXEN	
MAD6	VMD	Frame buffer depth
MAD5	CUR1	Color of graphic cursor
MAD4	CUR0	
MAD3	VCF3	MIVAC operating modes
MAD2	VCF2	
MAD1	VCF1	
MAD0	VCF0	

Figure 10 Attribute Control Codes

VCF0 – VCF3 (MAD0 – MAD3)

VCF0 to VCF3 (MAD0 to MAD3) define sixteen basic operating modes as shown in the tables 4 and 5.

Table 4 Operating Modes

Mode	ACRTC attribute code setting				Screen configuration (dots × rasters)	Frame buffer (bytes)	ACRTC Operating frequency (MHz)	Memory access	Access mode	Memory chips	DOTCLK			Maximum frequency (MHz)
	VCF3	VCF2	VCF1	VCF0							Color grada- tion	Shift (bits)	Division ratio	
0	0	0	0	0	640 × 200, 350, 400, 480	512 k/128 k	4.13	480 ns/ 4 times	Single access mode	1	B & W	16	1	33
1	0	0	0	1	640 × 200, 480 × 240, 320 × 200, 240						4	8	2	16.5
2	0	0	1	0	320 × 200, 240 256 × 192						16	4	4	8.25
3	0	0	1	1	640 × 200, 350, 400, 480	1 M/256 k				2	4	16	1	33
4	0	1	0	0	640 × 200 480 × 240, 320 × 200, 240						16	8	2	16.5
5	0	1	0	1	640 × 200, 350, 400, 480	2 M/512 k				4		16	1	33
6	0	1	1	0	640 × 200, 480 × 240, 320 × 200, 240	512 k/128 k			Dual access mode 0	1	B & W		2	16.5
7	0	1	1	1	320 × 200, 240 256 × 192						4	8	4	8.25
8	1	0	0	0	640 × 200, 350, 400, 480	1 M/256 k				2	B & W	32	1	33
9	1	0	0	1	640 × 200, 480 × 240, 320 × 200, 240						4	16	2	16.5
A	1	0	1	0	320 × 200, 240 256 × 192						16	8	4	8.25
B	1	0	1	1	640 × 200, 350, 400, 480	2 M/512 k				4	4	32	1	33
C	1	1	0	0	640 × 200, 480 × 240, 320 × 200, 240						16	16	2	16.5
D	1	1	0	1	640 × 200, 350, 400, 480	512 k/128 k		960 ns/ 16 times	Single access mode	1	4	32	1	33
E	1	1	1	0	640 × 200, 480 × 240, 320 × 200, 240						16	16	2	16.5
F	1	1	1	1	640 × 200, 350, 400, 480	1 M/256 k				2		32	1	33

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**Table 5 Dot Clock Frequency Range**

Mode	Frequency
0, 3, 5, 8, B, D, F	33 – 11 MHz
1, 4, 6, 9, C, E	16.5 – 5.5 MHz
2, 7, A	8.25 – 2.75 MHz

**MCYC fetch:** The MCYC fetch defines the number of cycles.

- 1: One, two, or four memories
- 2: One or two memories

**Access mode:** The MIVAC supports single- and dual-access 0 modes.

- 1: Single access/dual access 0
- 2: Single access

**Memory chips:** The MIVAC can connect one, two, or four memory chips.

- 1 chip: connect FD0 to FD3 to data bus
- 2 chips: connect FD0 to FD8 to data bus
- 3 chips: connect FD0 to FD7 to low-order 8 bits, and MAD8 to MAD15 to high-order 8 bits of data bus.

**Bit/pixel:** The MIVAC can display:

- 1 bit/pixel (B and W)
- 2 bits/pixel (4 colors)
- 4 bits/pixel (16 colors)

**Dot shift:** The MIVAC can shift by 4, 8, 16, or 32 dots.

**DOTCLK division:** The MIVAC can divide the INCLK frequency by 1, 2 or 4 depending on the number of shifted dots and access modes.

### **CUR0 and CUR1 (MAD4 and MAD5)**

CUR0 and CUR1 set the cursor color (table 6).

### **VMD0 (MAD6)**

VMD0 selects memory chips (table 7).

### **MUXEN (MAD7)**

MUXEN selects the multiplex video output. Multiplexing is defined by MUXEN and VSYNC/2 (table 8). VSYNC/2 is obtained by dividing VSYNC from the ACRTC by 2.

Note: VIDEOD is not multiplexed.

### **BLINK1 (MA18)**

BLINK1 defines the blinking of cursor (table 9).

### **BLINK2 (MA19)**

BLINK2 controls  $\overline{BL2IRQ}$  output. When BLINK2 is 1,  $\overline{BL2IRQ}$  is asserted (low).

**Table 6 Cursor Color**

CUR1	CUR0	Cursor color
0	0	Black (VIDEOA to VIDEOD = 0)
0	1	White (VIDEOA to VIDEOD = 1)
1	0	Color specified by each bit (VIDEOA to VIDEOD) is inverted.
1	1	Color specified by each bit (VIDEOA to VIDEOD) is inverted. (VIDEOD is not changed.)

**Table 7 Memory Chips**

VMD	Memory chips
0	256 k words × 4 bit DRAM
1	1 M words × 4 bit DRAMs

**Table 8 Video Multiplex**

MUXEN	VSYNC/2	VIDEOA	VIDEOD
0	0	A	B
	1	A	B
1	0	A	B
	1	C	D

**Table 9 Cursor Blink**

BLINK1	Cursor
0	No blinking
1	Blinking

**Table 10 Absolute Maximum Ratings**

Item	Symbol	Rating	Unit
Supply voltage	$V_{CC}$ (Note)	-0.3 to +7.0	V
Input voltage	$V_{in}$ (Note)	-0.3 to $V_{CC} + 0.3$	V
Output Voltage	$V_{out}$ (Note)	5.5	V
Operating temperature	$T_{opr}$	0 to +70	°C
Storage temperature	$T_{stg}$	-55 to +150	°C

Note: This value is in reference to  $V_{SS} = 0$  V.

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**Table 11 Recommended Operating Conditions**

Item	Symbol	Min	Typ	Max	Unit
Supply voltage	$V_{CC}$ (Note)	4.75	5.00	5.25	V
Input "Low" level voltage	$V_{IL}$ (Note)	0	—	0.7	V
Input "High" level voltage	$V_{IH}$ (Note)	2.2	—	$V_{CC}$	V
Operating temperature	$T_{opr}$	0	25	70	°C

Note: This value is in reference to  $V_{SS} = 0$  V.

## Electrical Characteristics

**Table 12 DC Characteristics** ( $V_{CC} = 5.0$  V  $\pm$  5%,  $V_{SS} = 0$  V,  $T_a = 0$  to  $+70^\circ\text{C}$  unless otherwise noted.)

Item		Symbol	Min	Max	Unit	Test condition
Input "High" level voltage	All inputs	$V_{IH}$	2.2	$V_{CC}$	V	
Input "Low" level voltage	All inputs	$V_{IL}$	-0.3	0.7	V	
Input clamp voltage	All inputs	$V_I$	—	-1.5	V	$V_{CC} = 4.75$ V $I_{in} = 18$ mA
Output "High" level voltage	All outputs	$V_{OH}$	2.7	—	V	$V_{CC} = 4.75$ V $I_{OH} = -400$ $\mu\text{A}$
Output "Low" level voltage	All outputs	$V_{OL}$	—	0.5	V	$V_{CC} = 4.75$ V $I_{OL} = 8$ mA
"High" level input current	All inputs	$I_{IH}$	—	20	$\mu\text{A}$	$V_{CC} = 5.25$ V $V_I = 2.7$ V
"Low" level input current	All inputs	$I_{IL}$	—	-400	$\mu\text{A}$	$V_{CC} = 5.25$ V $V_I = 0.4$ V
Short circuit output current	All outputs	$I_{OS}$	-40	-120	mA	$V_{CC} = 5.25$ V
Supply current		$I_{CC}$	—	120	mA	$V_{CC} = 5.25$ V

**Table 13 AC Characteristics** ( $V_{CC} = 5.0\text{ V} \pm 5\%$ ,  $V_{SS} = 0\text{ V}$ ,  $T_a = 0\text{ to }+70^\circ\text{C}$  unless otherwise noted.)

No.	Item	Symbol	Reference figure no.	Min	Max	Unit
1	INCLK cycle time	$t_C$	11	30	—	ns
2	INCLK high level pulse width	$t_{WH}$	11	12	—	ns
3	INCLK low level pulse width	$t_{LW}$	11	12	—	ns
4	INCLK rise time	$t_R$	11	—	5	ns
5	INCLK fall time	$t_F$	11	—	5	ns
6	2CLK delay time	$t_{2CLKD}$	11	—	15	ns
7	MCYC setup time	$t_{MCYCS}$	11	10	—	ns
8	MCYC hold time	$t_{MCYCH}$	11	0	—	ns
9	HSYNC setup time	$t_{HSS}$	11	15	—	ns
10	HSYNC hold time	$t_{HSH}$	11	0	—	ns
11	DISP1 setup time	$t_{DISPS}$	11	20	—	ns
12	MRD setup time	$t_{MRDS}$	11	15	—	ns
13	MRD hold time	$t_{MRDH}$	11	5	—	ns
14	DRAW setup time	$t_{DRAWS}$	11	15	—	ns
15	DRAW hold time	$t_{DRAWH}$	11	5	—	ns
16	$\overline{AS}$ setup time	$t_{ASS}$	11	20	—	ns
17	$\overline{AS}$ pulse width	$t_{ASW}$	11	25	—	ns
18	Memory address setup time	$t_{AS}$	11	25	—	ns
19	Memory address hold time	$t_{AH}$	11	0	—	ns
20	$\overline{CUD1}$ setup time	$t_{CUDS}$	11	5	—	ns
21	$\overline{VSYNC}$ setup time	$t_{VSS1}$	17	5	—	ns
22	Attribute code delay time	$t_{ACS}$	20	—	100	ns
23	Attribute code hold time	$t_{ASH}$	20	5	—	ns
24	$\overline{RAS}$ delay time	$t_{RSD}$	11	—	15	ns
25	$\overline{RAS}$ precharge time	$t_{RSP}$	11	3tc-10	—	ns
26	$\overline{CS}$ delay time 1	$t_{CSDL}$	11	—	15	ns
27	$\overline{OE}$ delay time 1	$t_{OED1}$	11	—	15	ns
28	2CLK delay time from $\overline{OE}$	$t_{2CKD}$	11	0	10	ns
29	Valid MAD0 – MA19 to valid low address delay time	$t_{RAD}$	11	—	25	ns

## HD63487

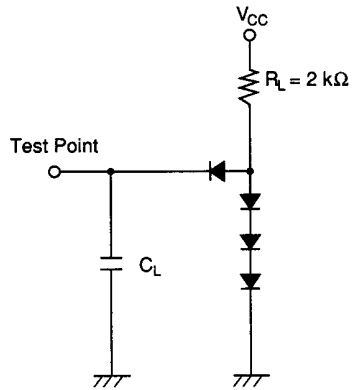
AC Characteristics ( $V_{CC} = 5.0 \text{ V} \pm 5\%$ ,  $V_{SS} = 0 \text{ V}$ ,  $T_a = 0$  to  $+70^\circ\text{C}$  unless otherwise noted.) (cont)

No.	Item	Symbol	Reference figure no.	Min	Max	Unit
30	Column address delay time	$t_{CAD}$	11	5	25	ns
31	FD setup time	$t_{FDS}$	11	8	—	ns
32	FD hold time 1	$t_{FDH1}$	11	5	—	ns
33	FD hold time 2	$t_{FDH2}$	11	2	—	ns
34	Valid FD to valid MAD delay	$t_{MADV}$	11	—	10	ns
35	Read data turn on time	$t_{RDTV}$	11	0	—	ns
36	Read data hold time	$t_{RDH}$	11	3	—	ns
37	WE delay time	$t_{WED}$	14	—	25	ns
38	WE low pulse width	$t_{WLW}$	14	$t_c - 15$	—	ns
39	WE high pulse width	$t_{WHW}$	14	$t_c - 15$	—	ns
40	$\overline{CE}$ low to WE pulse width	$t_{CWEW}$	14	$t_c - 15$	—	ns
41	Draw write data setup time	$t_{WDS}$	14	15	—	ns
42	FD delay time 1	$t_{FDD1}$	14	—	20	ns
43	FD delay time 2	$t_{FDD2}$	14	—	20	ns
44	WE/ $\overline{CS}$ low to FD hold time	$t_{WFDHW}$	14	$t_c - 10$	—	ns
45	WE/ $\overline{CS}$ low to address hold	$t_{WAHW}$	14	$t_c - 5$	—	ns
46	FD hold time	$t_{FDHW}$	14	0	—	ns
47	FD turn off time	$t_{FDTI}$	14	—	50	ns
48	VSYNC/2 delay time	$t_{VS2D}$	11	—	25	ns
49	DOTCLK delay time	$t_{DCD}$	11	—	15	ns
50	VIDEO delay time	$t_{VD}$	11	-5	5	ns
51	BL2IRQ delay time	$t_{IRQD}$	20	—	10	ns
52	IRQCLR to BL2IRQ clear delay time	$t_{IRQCD}$	20	—	20	ns
53	SHTEN delay time	$t_{SFTEND}$	11	-5	5	ns



Test Circuit

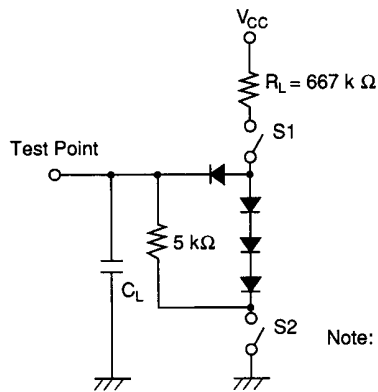
(a) Totem pole output



Note: All diodes are 1S2074®'s or the equivalent.

Signal	CL (pF)
2CLK	40
DOTCK	
VSYNC/2	
RAS	
CS	
WE	
OE	
FA0 – FA9	
VIDEOA – VIDEOD	
SHFTEN	
BL2IRQ	

(b) Three state output



Note: All diodes are 1S2074®'s or the equivalent.

Signal	CL (pF)
MAD0 – MAD15	40
FD0 – FD7	

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**HD63487**

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**Table 14 Reference**

<b>Display data fetch</b>	<b>Memory chip</b>	<b>Cycle mode</b>	<b>Figure no.</b>
4 fetch/1 MCYC	1 chip	Drawing read cycle	11
		Drawing write cycle	14
		Display cycle	17
		Refresh and attribute cycle	20
	2 chips	Drawing read cycle	12
		Drawing write cycle	15
		Display cycle	17
		Refresh and attribute cycle	20
	4 chips	Drawing read cycle	13
		Drawing write cycle	16
		Display cycle	18
		Refresh and attribute cycle	20
16 fetch/2 MCYC	1 chip	Drawing read cycle	11
		Drawing write cycle	14
		Display cycle	19
		Refresh and attribute cycle	20
	2 chips	Drawing read cycle	12
		Drawing write cycle	15
		Display cycle	19
		Refresh and attribute cycle	20

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Timing Chart

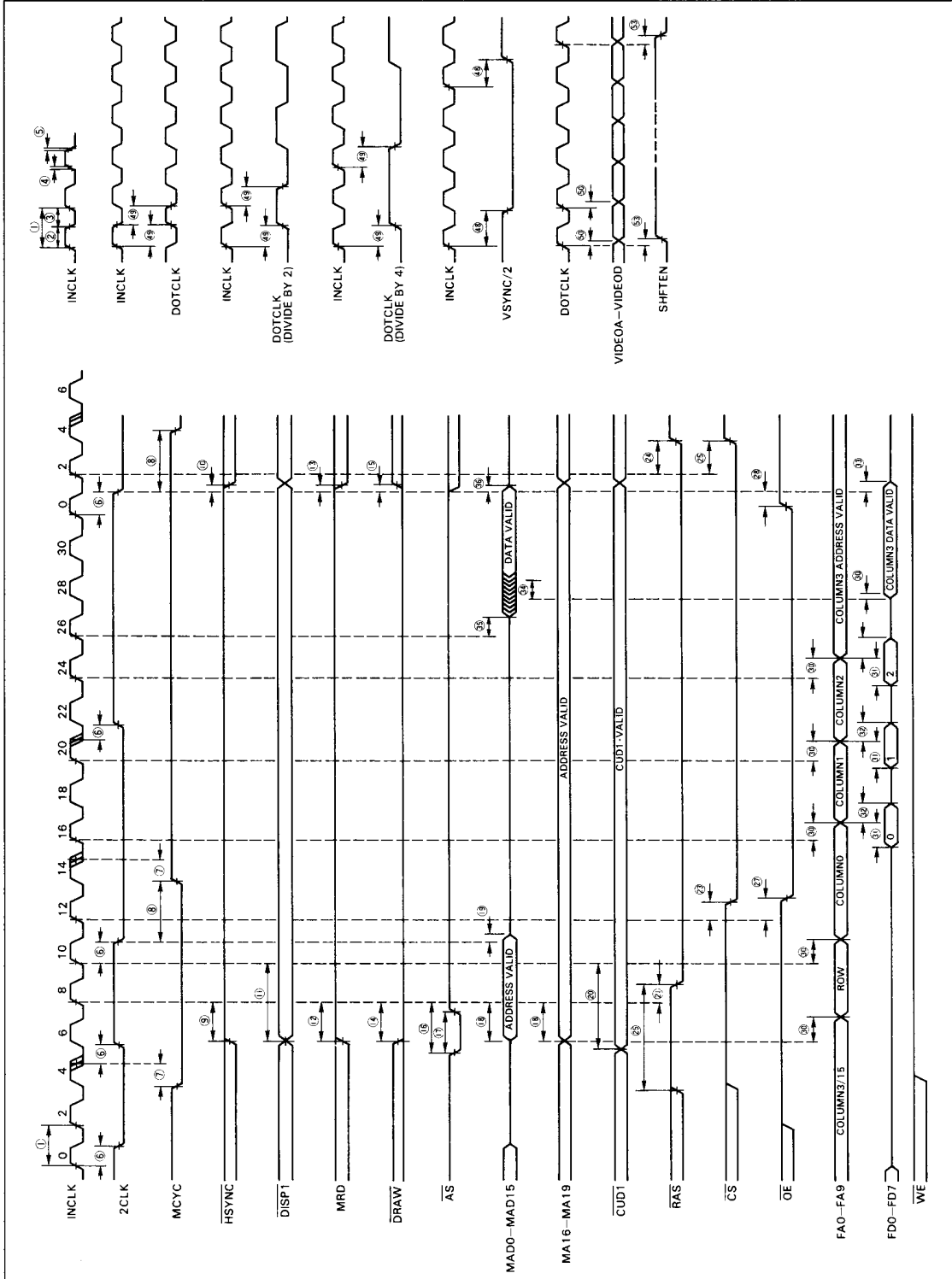


Figure 11 1M1CYC Draw Read (1 Chip)

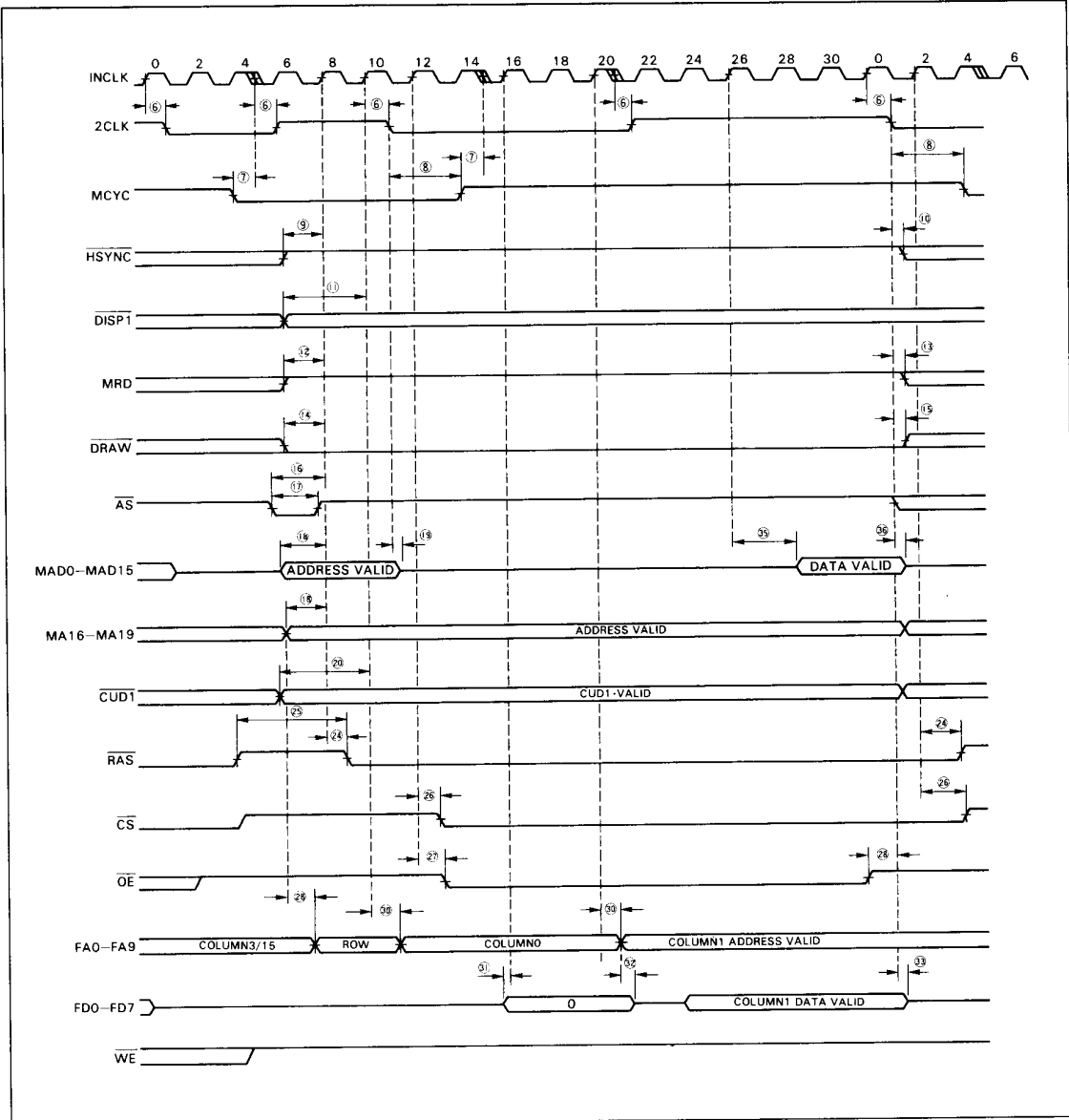


Figure 12 1MCYC Draw Read (2 Chips)

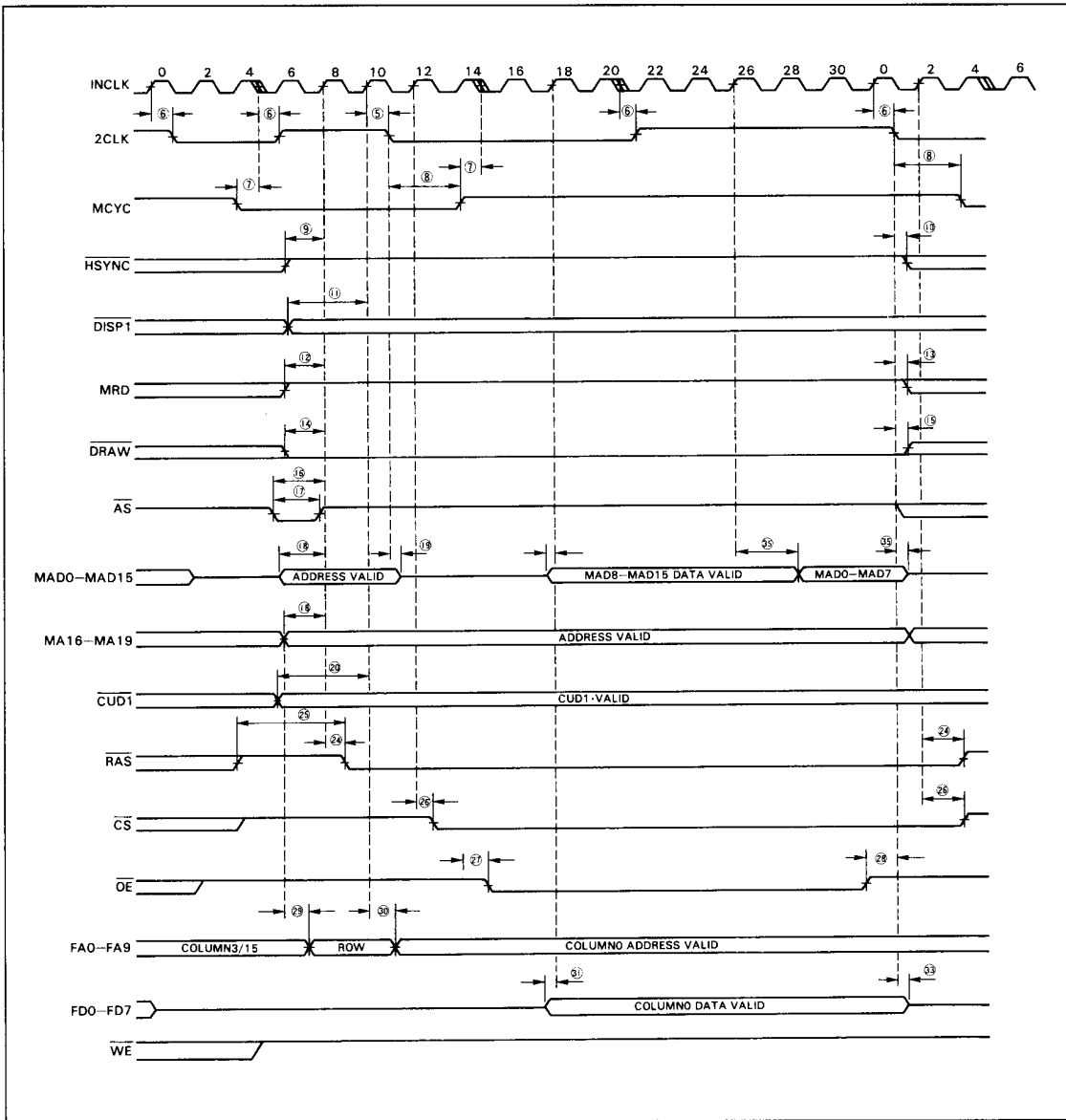


Figure 13 1M1CYC Draw Read (4 Chips)

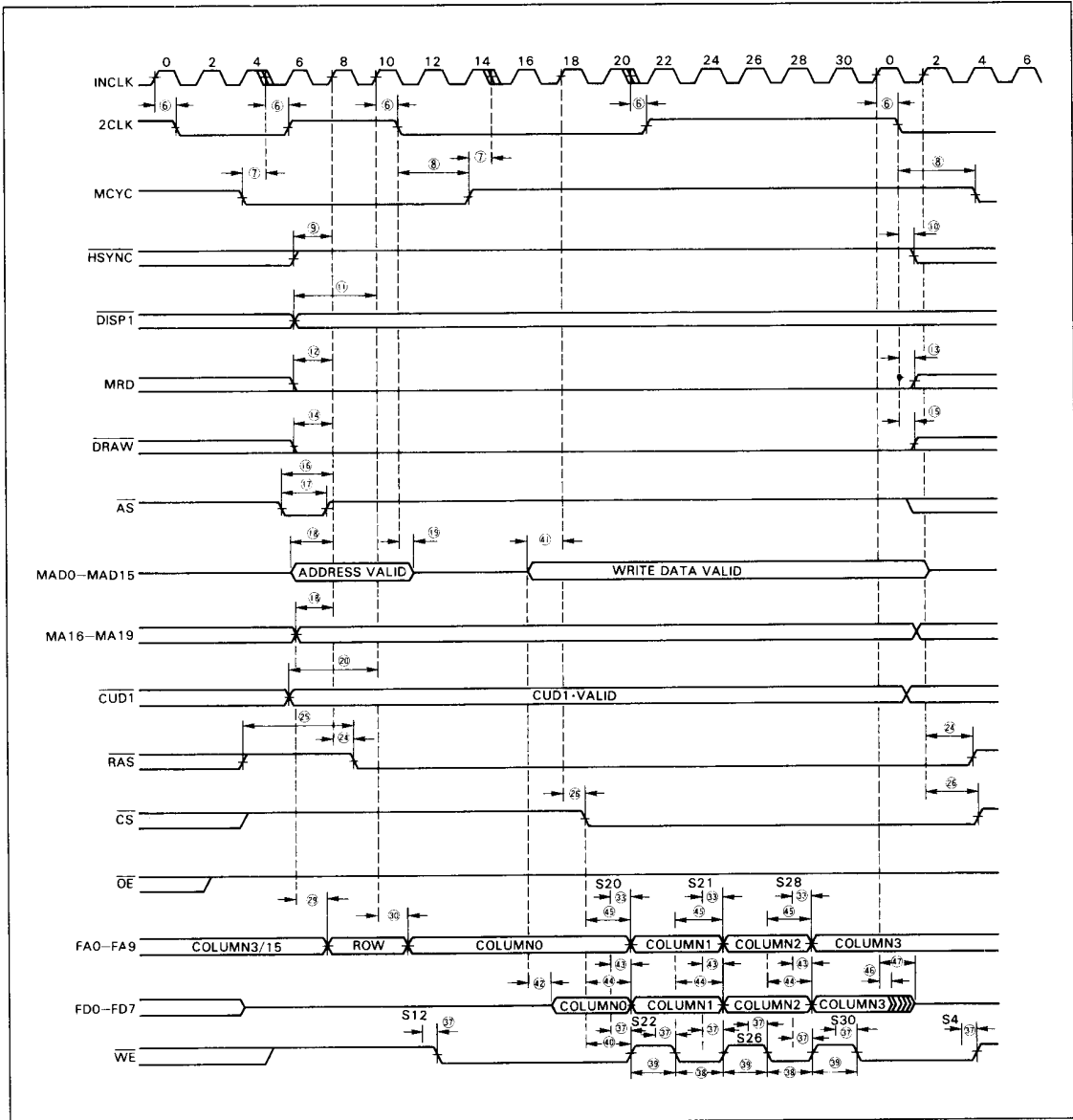


Figure 14 1M CYC Draw Write (1 Chip)

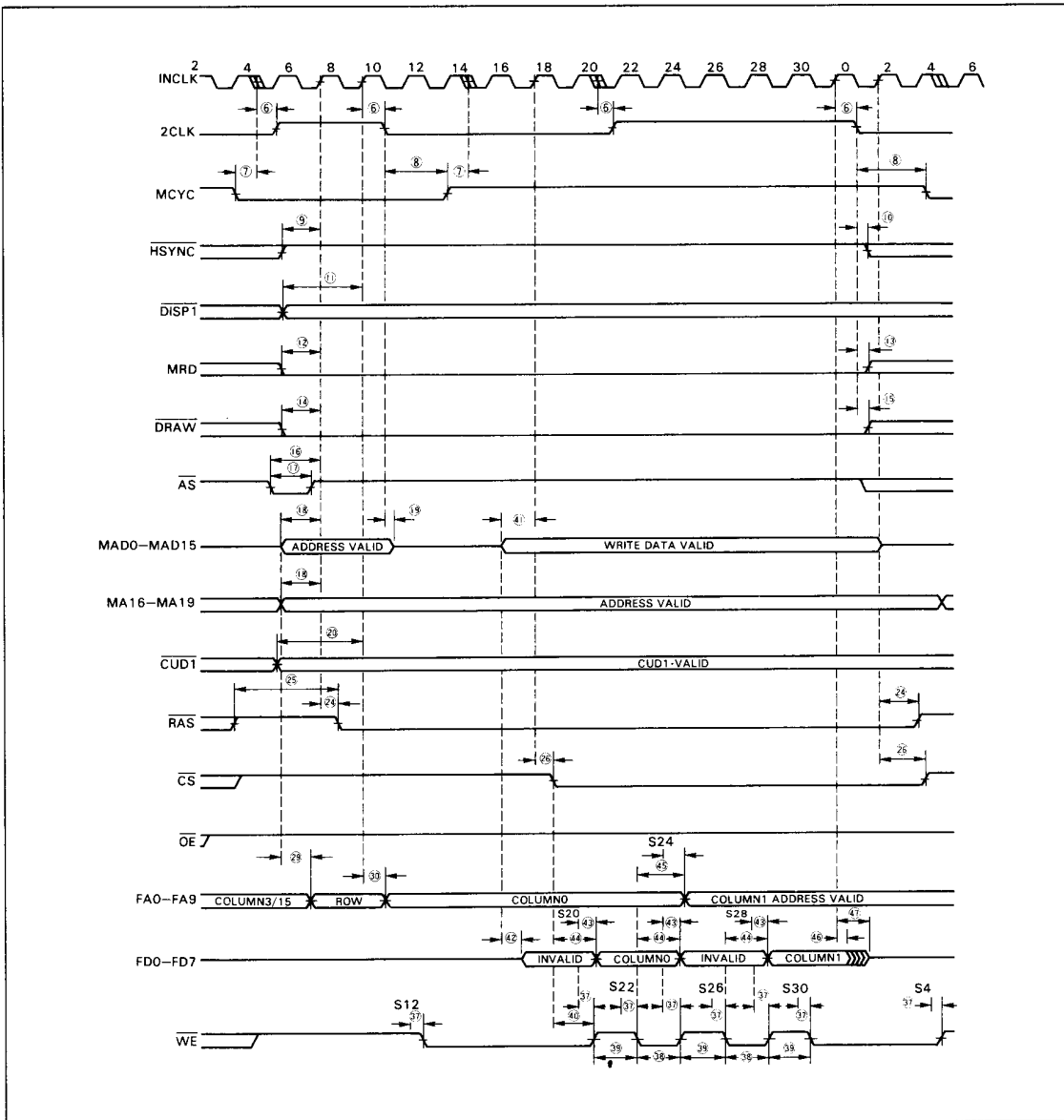


Figure 15 1MCYC Draw Write (2 Chips)

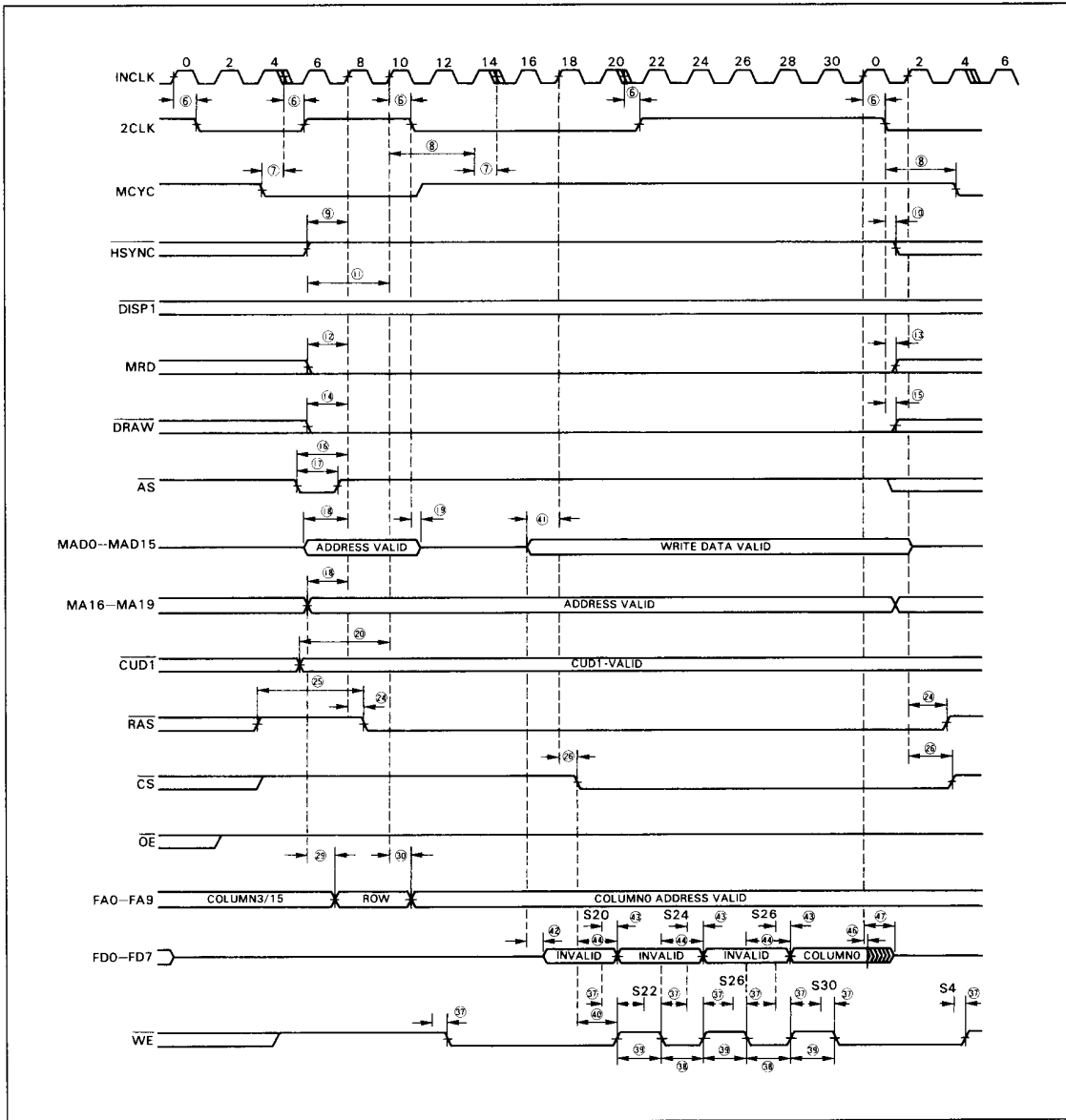


Figure 16 1MCYC Draw Write (4 Chips)



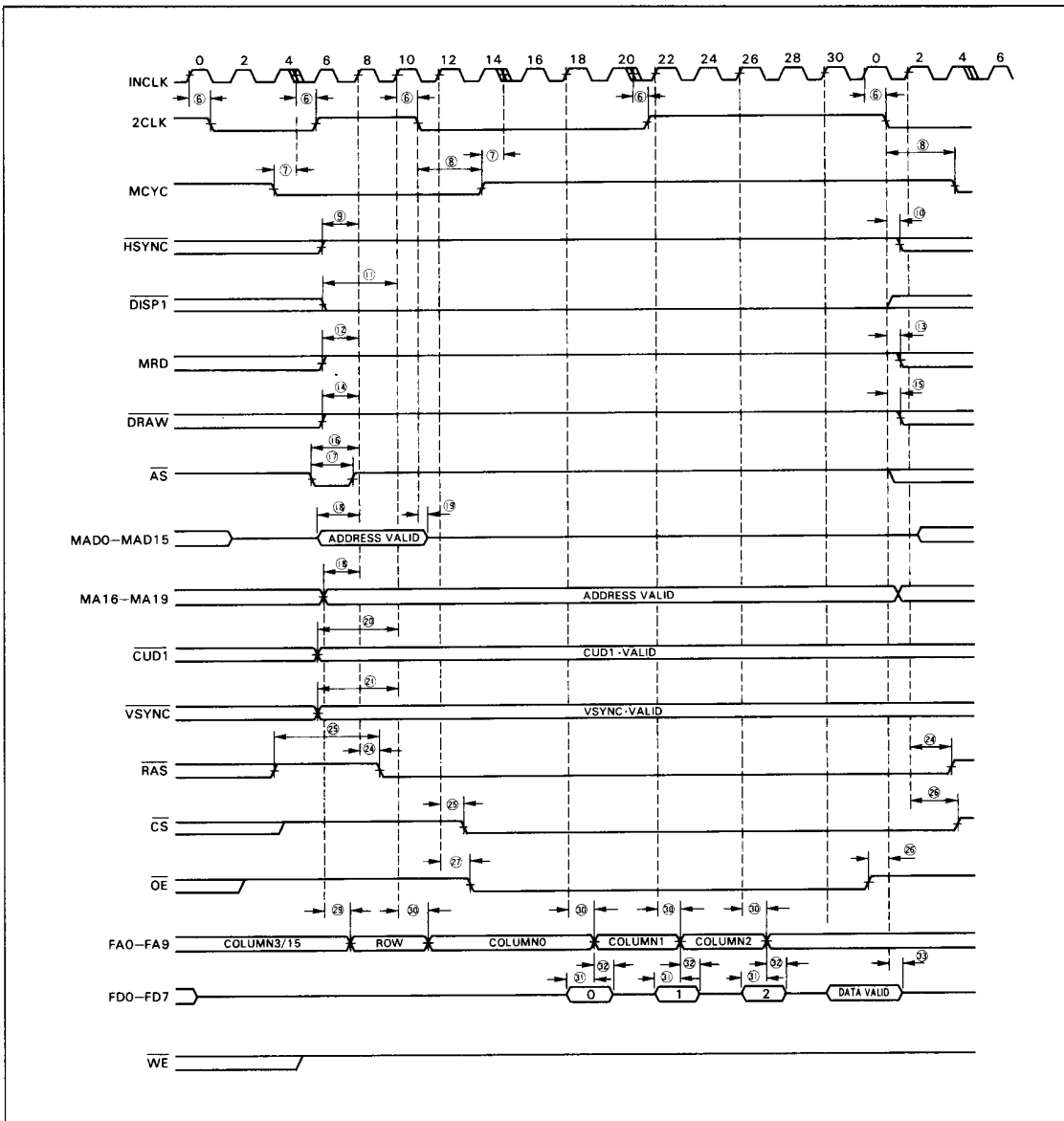


Figure 17 1MCMC Display Read (1 or 2 Chips)

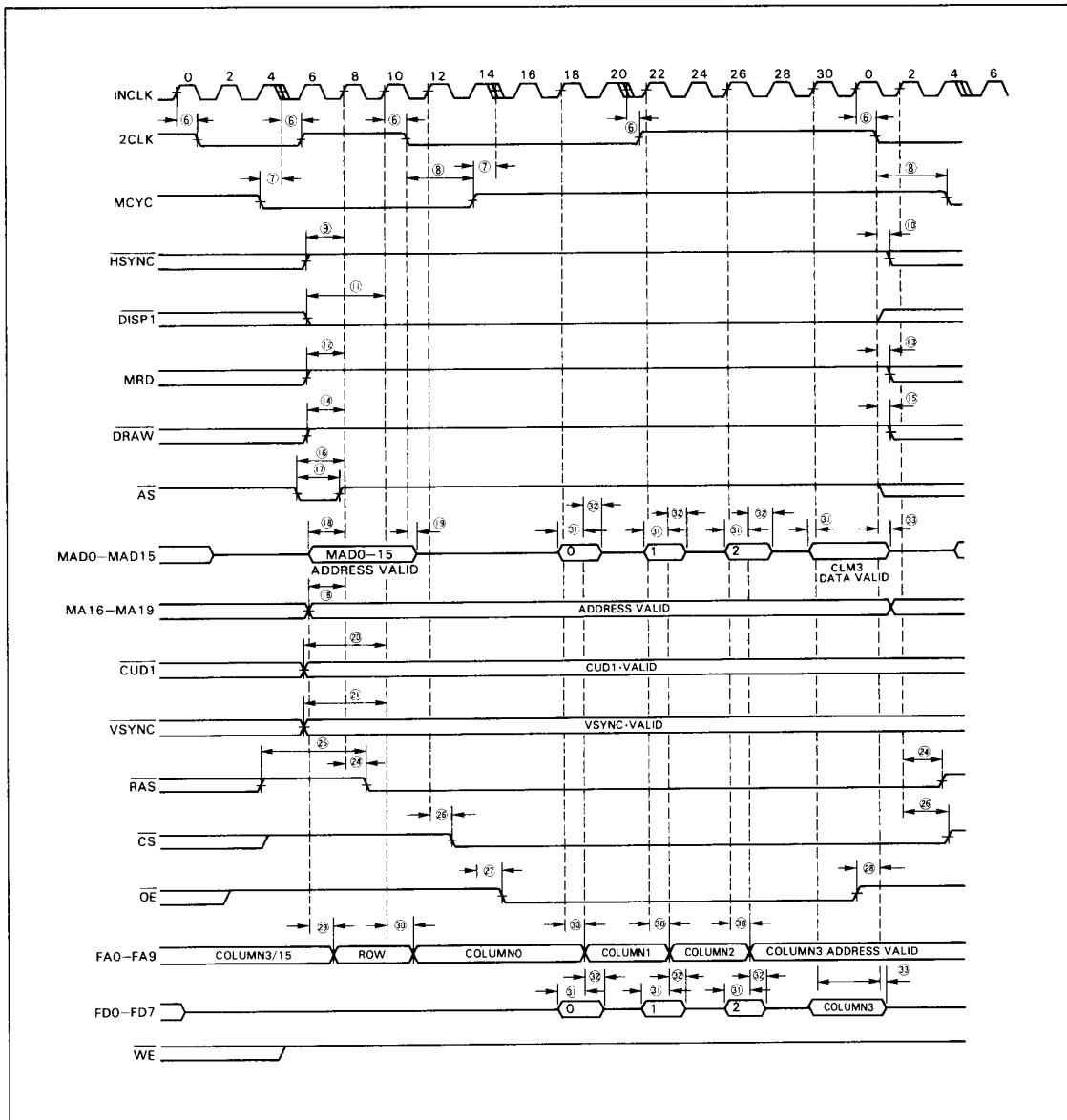


Figure 18 1M1CYC Display Read (4 Chips)

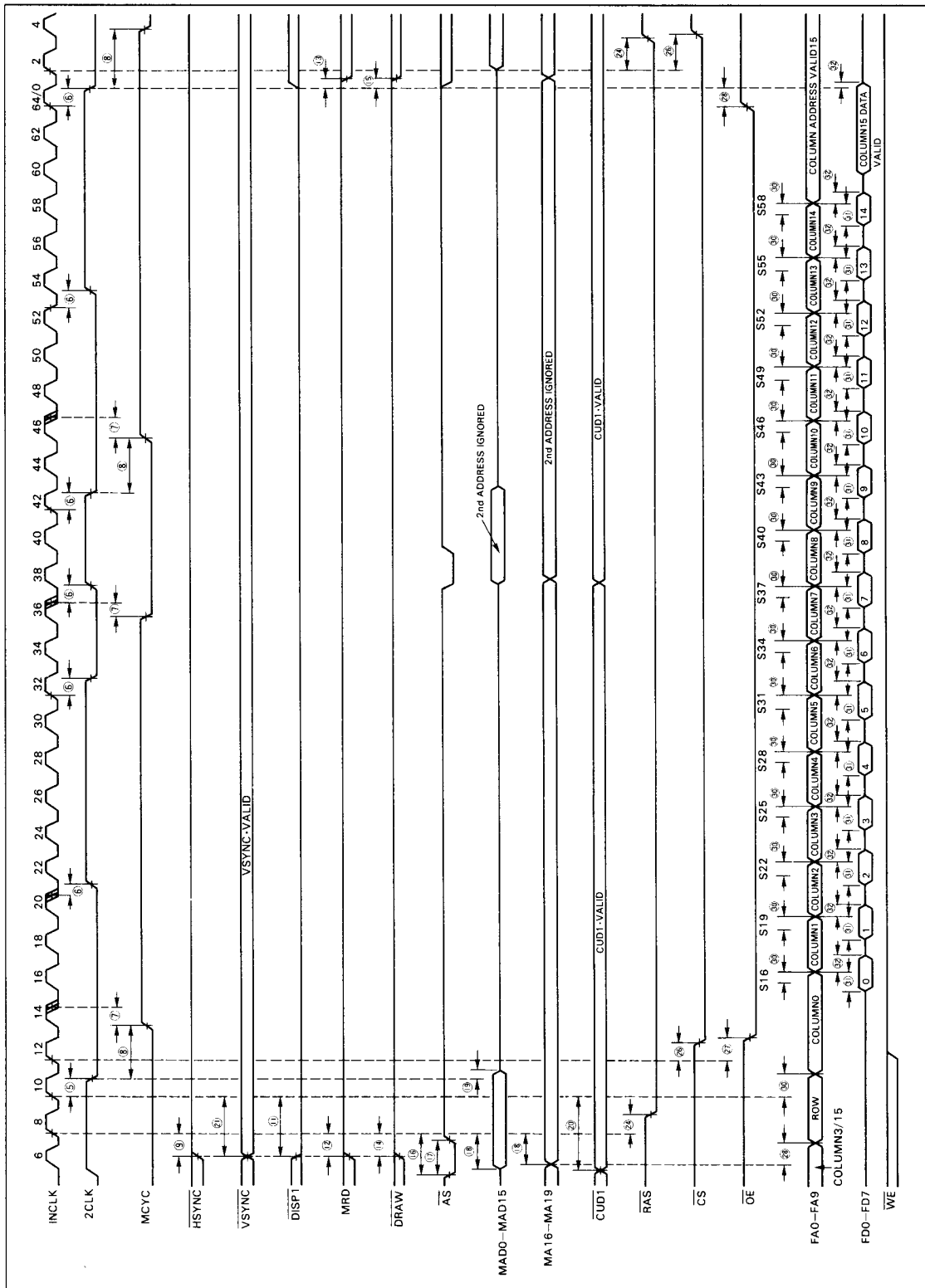


Figure 19 1MCMC Display Read (1 or 2 Chips)

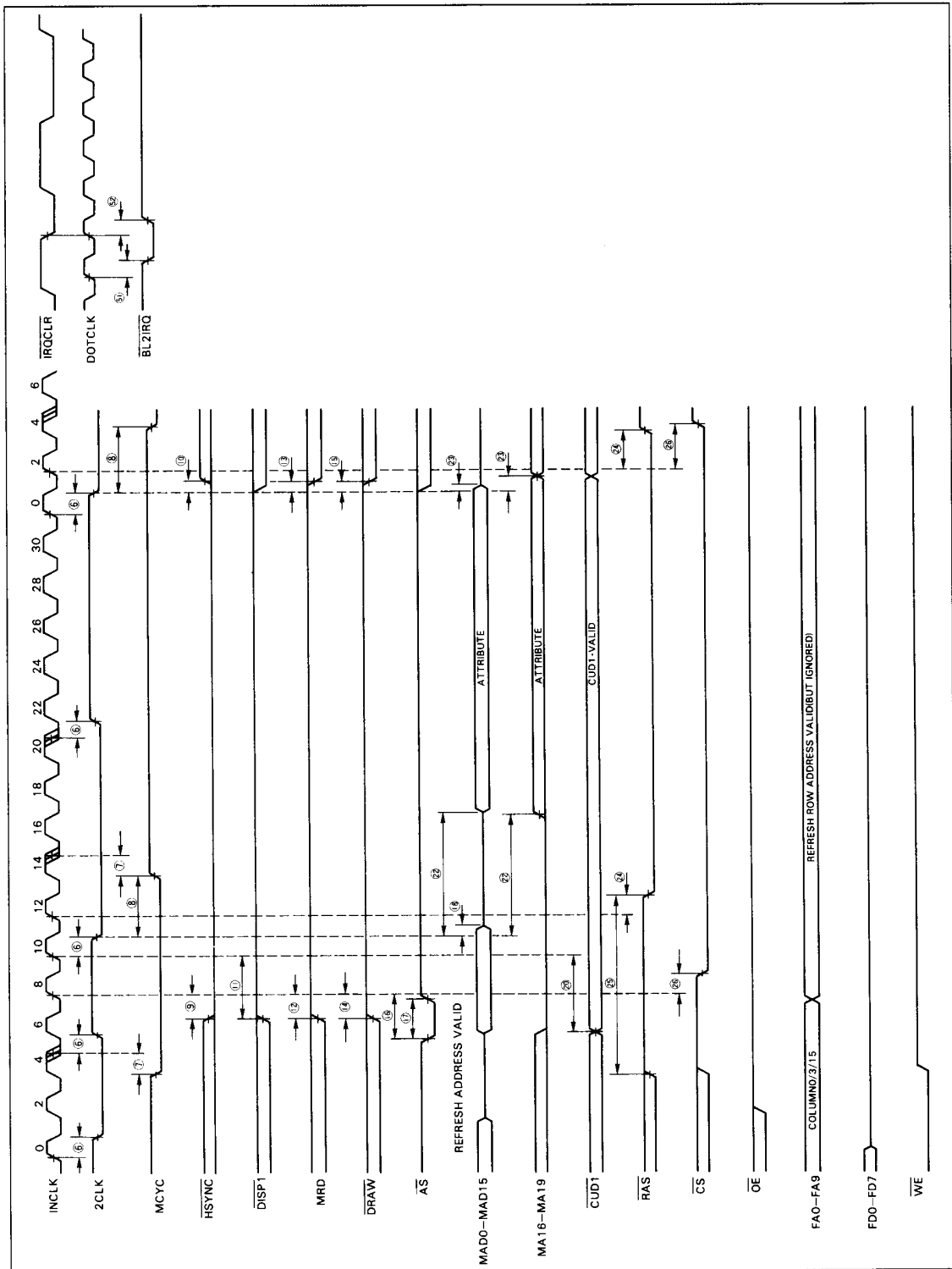
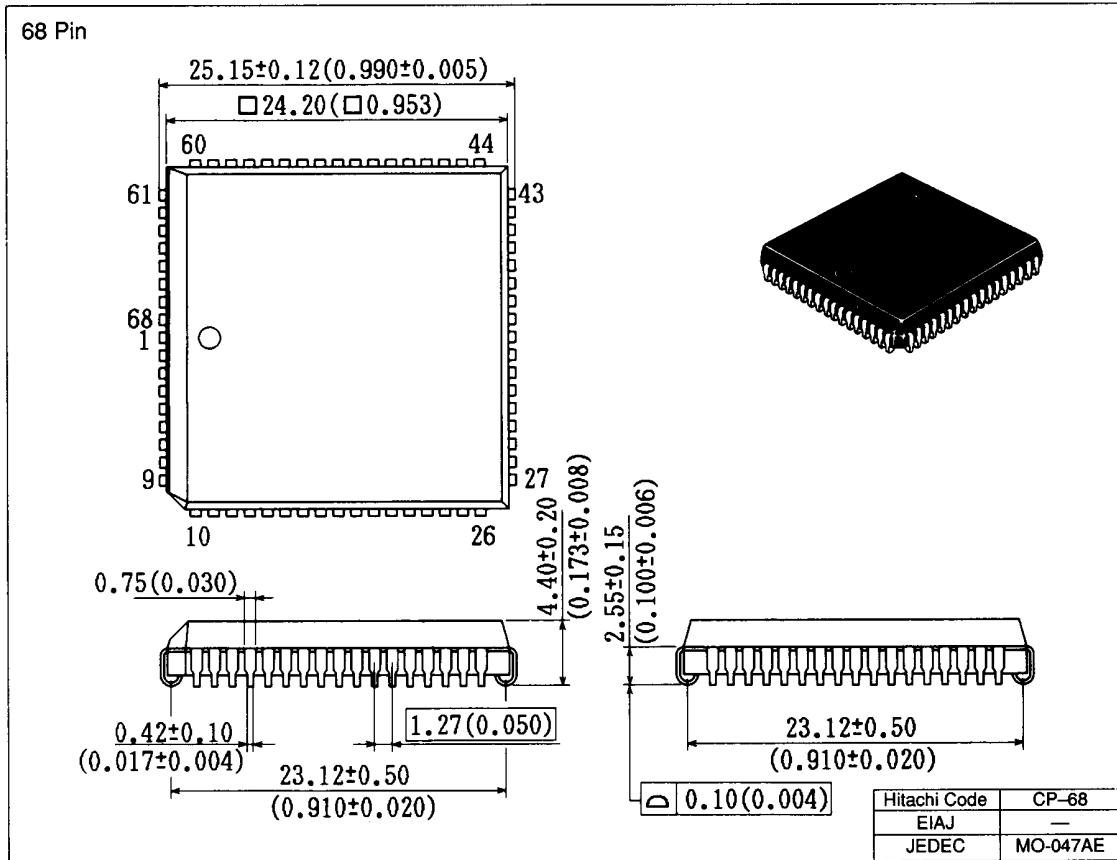


Figure 20 CS before RAS Refresh

Refer to application note (No. ADE-507-001) for detail of this product.

Package Dimensions

Unit: mm (inch)



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